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This index covers all technical items - papers, correspondence, reviews, etc. - that appeared in this periodical during 1996, and items from previous years that were commented upon or corrected in 1996.

The Author Index contains the primary entry for each item, listed under the first author's name, and cross-references from all coauthors. The Subject Index contains several entries for each item under appropriate subject headings, and subject cross-references.

It is always necessary to refer to the primary entry in the Author Index for the exact title, coauthors, and comments/corrections.

AUTHOR INDEX

A

- Abbiate, J.-C.**, *see* Deutsch, A., *T-CPMB* May 96 331-337
Abernethy, C.E., A.C. Cangellaris, and J.L. Prince. A novel method of measuring microelectronic interconnect transmission line parameters and discontinuity equivalent electrical parameters using multiple reflections; *T-CPMB* Feb 96 32-39
Ainspan, H.A., *see* Deutsch, A., *T-CPMB* May 96 331-337
Amagai, M. Effect of adhesive surface chemistry and morphology on package cracking in tapeless lead-on-chip (LOC) packages; *T-CPMB* May 96 301-309
Ambrosy, A., *see* De pestel, G., *T-CPMB* Feb 96 116-123
Angenieux, G., *see* Salik, R., *T-CPMB* Feb 96 74-81
Anigbo, F.C.J., S.D. Robinson, S.L. Broutin, G.J. Shevchuk, and D. Stefanik. Design of a compact, high speed optical transceiver using two step overmolding; *T-CPMB* Aug 96 562-568
Armendariz, M.G., *see* Kravitz, S.H., *T-CPMB* Feb 96 83-89
Artus, R.G.C. Measurements of the novel thermal conduction of a porphritic heat sink paste; *T-CPMB* Aug 96 601-604
Avanic, B.L., *see* Roy, S.K., *T-CPMB* May 96 444-451
Avedisian, C.T., *see* Fisher, T.S., *T-CPMB* Feb 96 255-262

B

- Baggerman, A.F.J.**, J.F.J.M. Caers, J.J. Wondergem, and A.G. Wagemans. Low-cost flip-chip on board; *T-CPMB* Nov 96 736-746
Banerji, K., *see* Bradley, E., *T-CPMB* May 96 320-330
Barrett, J., *see* Kelly, G., *T-CPMB* May 96 296-300
Basavanahally, N.R., M.F. Brady, and D.B. Buchholz. Optoelectronic packaging of two-dimensional surface active devices; *T-CPMB* Feb 96 107-115
Bathey, K., M. Swaminathan, L.D. Smith, and T.J. Cockerill. Noise computation in single chip packages; *T-CPMB* May 96 350-360
Bauer, T.M., *see* Kravitz, S.H., *T-CPMB* Feb 96 83-89
Becker, W.D., *see* McCredie, B.D., *T-CPMB* Aug 96 461-472
Bedouani, M., D. Lambert, and K. Kurzweil. Electrical performance of interconnects in polyimide-copper thin-film multilayers on ceramic substrate; *T-CPMB* May 96 382-390
Benzoni, A.M., *see* Dautartas, M.F., *T-CPMB* Aug 96 554-561
Berg, H., *see* Ganeshan, G.S., *T-CPMB* Aug 96 581-584
Boudreau, R.A. Foreword [to the special section on contributions from the 7th National Meeting of the Lasers and Electro-optics Society (LEOS)]; *T-CPMB* Feb 96 82
Boudreau, R.A. Foreword: Optoelectronics [intro. to special section on contributions from the 45th Electronic Components and Technology Conference]; *T-CPMB* Aug 96 523
Bradley, E., and K. Banerji. Effect of PCB finish on the reliability and wettability of ball grid array packages; *T-CPMB* May 96 320-330
Brady, M.F., *see* Basavanahally, N.R., *T-CPMB* Feb 96 107-115
Brews, J.R., *see* Yang, Y., *T-CPMB* Feb 96 230-237
Brews, J.R., *see* Yaochao Yang, *T-CPMB* May 96 372-381
Brews, J.R., *see* Yaochao Yang, *T-CPMB* Aug 96 481-486
Brews, J.R., *see* Simunic, T., *T-CPMB* Nov 96 803-812
Brooke, M.A., *see* Jokerst, N.M., *T-CPMB* Feb 96 97-106
Broutin, S.L., *see* Dautartas, M.F., *T-CPMB* Aug 96 554-561

- Broutin, S.L.**, *see* Anigbo, F.C.J., *T-CPMB* Aug 96 562-568
Buchanan, B., *see* Jokerst, N.M., *T-CPMB* Feb 96 97-106
Buchholz, D.B., *see* Basavanahally, N.R., *T-CPMB* Feb 96 107-115

C

- Caers, J.F.J.M.**, *see* Baggerman, A.F.J., *T-CPMB* Nov 96 736-746
Callahan, J.J., *see* Rainer Dohle, G., *T-CPMB* Feb 96 57-63
Callahan, J.J., *see* Dohle, G.R., *T-CPMB* Aug 96 575-580
Cangellaris, A.C., *see* Abernethy, C.E., *T-CPMB* Feb 96 32-39
Cangellaris, A.C., *see* Celik, M., *T-CPMB* Feb 96 64-73
Cangellaris, A.C., *see* Celik, M., *T-CPMB* Aug 96 692
Canner, J.P., *see* Sakabe, Y., *T-CPMB* Feb 96 7-14
Celik, M., and A.C. Cangellaris. Efficient transient simulation of lossy packaging interconnects using moment-matching techniques; *T-CPMB* Feb 96 64-73
Celik, M., and A.C. Cangellaris. Correction to "Efficient transient simulation of lossy packaging interconnects using moment-matching techniques" (Feb 96 64-73); *T-CPMB* Aug 96 692
Chan, Y.C., *see* Xie, D.J., *T-CPMB* Feb 96 148-153
Chan, Y.C., *see* So, A.C.K., *T-CPMB* Aug 96 661-668
Chan, Y.C., *see* Xie, D.J., *T-CPMB* Aug 96 669-678
Chan, Y.C., *see* Xie, D.J., *T-CPMB* Aug 96 679-684
Chance, D., *see* Ho-Ming Tong, *T-CPMB* Feb 96 203-214
Chang, S.-Y., *see* Lin, K.-L., *T-CPMB* Nov 96 747-751
Chan Long Shieh, *see* Schwartz, D.B., *T-CPMB* Aug 96 532-539
Chao Fang-Lin, *see* Ruey-Bee Wu, *T-CPMB* May 96 397-402
Chen, J.-C., *see* Cheng, W.-H., *T-CPMB* Nov 96 764-769
Chen, S.-C.S., *see* Zu, L., *T-CPMB* Aug 96 635-643
Cheng, W.-H., W.-H. Wang, and J.-C. Chen. Defect formation mechanisms in laser welding techniques for semiconductor laser packaging; *T-CPMB* Nov 96 764-769
Chiba, T., M. Yamada, and F. Kobayashi. Limitation of the signal pin density on wiring boards; *T-CPMB* May 96 391-396
Chi-Taou Tsai, and Wai-Yeung Yip. An experimental technique for full package inductance matrix characterization; *T-CPMB* May 96 338-343
Chun, C.K.Y., *see* Schwartz, D.B., *T-CPMB* Aug 96 532-539
Cockerill, T.J., *see* Bathey, K., *T-CPMB* May 96 350-360
Cole, H.S., *see* Krishnamurthy, V.B., *T-CPMB* Feb 96 42-47
Coteus, P.W., *see* Deutsch, A., *T-CPMB* May 96 331-337
Coucoulas, A., *see* Dautartas, M.F., *T-CPMB* Aug 96 554-561
Cross, J., *see* Jokerst, N.M., *T-CPMB* Feb 96 97-106

D

- Dai, W.W.-M.**, *see* Darnauer, J., *T-CPMB* Feb 96 263
Daping Yao, and Jian Ku Shang. Effect of cooling rate on interfacial fatigue-crack growth in Sn-Pb solder joints; *T-CPMB* Feb 96 154-165
Darnauer, J., T. Ishiki, P. Garay, J. Ramirez, V. Maheshwari, and W.W.-M. Dai. Correction to "A silicon-on-silicon field programmable multichip module (FPMCM) - Integrating FPGA and MCM technologies" (Nov 95 601-608); *T-CPMB* Feb 96 263
Dautartas, M.F., A.M. Benzoni, S.L. Broutin, A. Coucoulas, D.T. Moser, Y.-H. Wong, and Yiu-Man Wong. Optical performance of low-cost self-aligned MCM-D based optical data links; *T-CPMB* Aug 96 554-561
DeFoster, S.M., *see* Subbarayan, G., *T-CPMB* Aug 96 685-691
Dekovic, Y., *see* Siala, S., *T-CPMB* Aug 96 548-553
De pestel, G., A. Ambrosy, Q. Tan, M. Vrana, F. Migom, H. Richter, J. Vandewege, and P. Vetter. Multichannel optical links compatible with the fiber-in-board technology; *T-CPMB* Feb 96 116-123
Deutsch, A., C.W. Surovic, A.P. Lanzetta, H.A. Ainspan, J.-C. Abbiate, A. Vichbeck, J.C. Hedrick, J.M. Shaw, S.L. Tisdale, E.F. Foster, and P.W. Coteus. Broadband characterization of low dielectric constant and low dielectric loss CYTUF cyanate ester printed circuit board material; *T-CPMB* May 96 331-337
Deutsch, A. Foreword: Contributions from the 4th Topical Meeting on Electrical Performance of Electronic Packaging [special section intro.]; *T-CPMB* Aug 96 460
Dohle, G.R., T.J. Drabik, J.J. Callahan, and K.P. Martin. Low temperature bonding of epitaxial lift off devices with AuSn; *T-CPMB* Aug 96 575-580
Drabik, T.J., *see* Rainer Dohle, G., *T-CPMB* Feb 96 57-63

- Drabik, T.J.**, see Dohle, G.R., *T-CPMB Aug 96* 575-580
Duchene, G.A., see Haugsjaa, P.O., *T-CPMB Feb 96* 90-96

E

- Elshabini-Riad, A.** Special section on microwave packaging; *T-CPMB Feb 96* 40-41

F

- Fang-Lin Chao**, see Ruey-Beei Wu, *T-CPMB May 96* 397-402
Ferrill, M.G., see Subbarayan, G., *T-CPMB Aug 96* 685-691
Fike, S., see Jokerst, N.M., *T-CPMB Feb 96* 97-106
Fisher, T.S., C.T. Avedisian, and J.P. Krusius. Transient thermal response due to periodic heating on a convectively cooled substrate; *T-CPMB Feb 96* 255-262
Flechet, B., see Salik, R., *T-CPMB Feb 96* 74-81
Fokken, G.J., see Schaefer, T.M., *T-CPMB May 96* 403-416
Foley, B.M., see Schwartz, D.B., *T-CPMB Aug 96* 532-539
Foster, E.F., see Deutsch, A., *T-CPMB May 96* 331-337
Frye, R.C., see Zu, L., *T-CPMB Aug 96* 635-643
Fu, W.S., see Yung-Cheng Lee, *T-CPMB Aug 96* 540-547

G

- Ganesan, G.S.**, G. Lewis, A. Woosley, W.S. Lindsay, and H. Berg. Level 1 crackfree plastic packaging technology; *T-CPMB Aug 96* 581-584
Garay, P., see Darnauer, J., *T-CPMB Feb 96* 263
George, A.G., J.P. Krusius, and R.F. Granitz. Packaging alternatives to large silicon chips: Tiled silicon on MCM and PWB substrates; *T-CPMB Nov 96* 699-708
Gerke, R.D., see Kromann, G.B., *T-CPMB Feb 96* 166-173
Gilbert, B.K., see Zabinski, P.J., *T-CPMB Feb 96* 215-224
Gilbert, B.K., see Schaefer, T.M., *T-CPMB May 96* 403-416
Gilbert, B.K., see Guang-Wen Pan, *T-CPMB Aug 96* 615-620
Gilbert, B.K., see Jilin Tan, *T-CPMB Aug 96* 621-627
Goetz, M.P. Time and frequency domain analysis of integral decoupling capacitors; *T-CPMB Aug 96* 518-522
Goland, D., see Ho-Ming Tong, *T-CPMB Feb 96* 203-214
Goodenough, N.J., see Stern, J.M., *T-CPMB Feb 96* 188-194
Gordon, C., and K.M. Roselle. Estimating crosstalk in multiconductor transmission lines; *T-CPMB May 96* 273-277
Govindarajan, M., see Siala, S., *T-CPMB Aug 96* 548-553
Granitz, R.F., see George, A.G., *T-CPMB Nov 96* 699-708
Guang-Tsai Lei, see Jilin Tan, *T-CPMB Aug 96* 621-627
Guang-Wen Pan, M. Toupkov, and B.K. Gilbert. A combined finite difference and analytic expression approach to crossover capacitance in a multilayer dielectric environment; *T-CPMB Aug 96* 615-620
Guang-Wen Pan, see Jilin Tan, *T-CPMB Aug 96* 621-627

H

- Hao Jie**, see Jie Hao, *T-CPMB Aug 96* 512-517
Harada, Y., see Uda, H., *T-CPMB Feb 96* 182-187
Hartman, D.H., see Schwartz, D.B., *T-CPMB Aug 96* 532-539
Hata, S., see Tsunetsugu, H., *T-CPMB Aug 96* 569-574
Haugsjaa, P.O., G.A. Duchene, J.F. Mehr, A.J. Negri, and M.J. Tabasky. Silicon waferboard-based single-mode optical fiber interconnects; *T-CPMB Feb 96* 90-96
Hayashi, M., see Sakabe, Y., *T-CPMB Feb 96* 7-14
Hedrick, J.C., see Deutsch, A., *T-CPMB May 96* 331-337
Heinrich, S.M., S. Shakya, Y. Wang, P.S. Lee, and S.A. Schroeder. Improved yield and performance of ball-grid array packages: design and processing guidelines for uniform and nonuniform arrays; *T-CPMB May 96* 310-319
Higashino, T., see Uda, H., *T-CPMB Feb 96* 182-187
Hileman, B., see Tien-Yu Tom Lee, *T-CPMB Feb 96* 131-137
Hirai, T., see Uda, H., *T-CPMB Feb 96* 182-187
Ho-Ming Tong, D. Goland, and D. Chance. Theory of pressure sintering of glass ceramic multichip carriers; *T-CPMB Feb 96* 203-214
Honnou, H., see Kurata, K., *T-CPMB Aug 96* 524-531
Hosoya, M., see Tsunetsugu, H., *T-CPMB Aug 96* 569-574
Hsieh, M., see Stoffel, N.C., *T-CPMB May 96* 417-422
Huang, C., Y. Yang, and J.L. Prince. A simultaneous switching noise design algorithm for leadframe packages with or without ground plane; *T-CPMB Feb 96* 15-22
Huang Wayne Wei-Xi, see Kromann, G.B., *T-CPMB Feb 96* 166-173
Hui, I.K., see Xie, D.J., *T-CPMB Aug 96* 669-678
Hui, I.K., see Xie, D.J., *T-CPMB Aug 96* 679-684

- Hwang, N.**, see Song, M.K., *T-CPMB Nov 96* 758-763

I

- Inoue, Y.**, see Tsunetsugu, H., *T-CPMB Aug 96* 569-574
Ishibashi, K., and J. Kimura. A new anisotropic conductive film with arrayed conductive particles; *T-CPMB Nov 96* 752-757
Ishikawa, S., see Kurata, K., *T-CPMB Aug 96* 524-531
Isshiki, T., see Darnauer, J., *T-CPMB Feb 96* 263
Ivey, P.A., see Stern, J.M., *T-CPMB Feb 96* 188-194

J

- Janko, B.**, see Jyh-Ming Jong, *T-CPMB Feb 96* 48-56
Jenshan Lin, see Zu, L., *T-CPMB Aug 96* 635-643
Jewell, J.L., see Yung-Cheng Lee, *T-CPMB Aug 96* 540-547
Jian Ku Shang, see Daping Yao, *T-CPMB Feb 96* 154-165
Jie Hao, A. Richter, J. Laskar, M. Swaminathan, and J. Mosley. Characterization of a small peripheral array package; *T-CPMB Aug 96* 512-517
Jilin Tan, Guang-Wen Pan, Guang-Tsai Lei, and B.K. Gilbert. Full wave analysis of transmission lines in a multilayer substrate with heavy dielectric losses; *T-CPMB Aug 96* 621-627
Johan Liu, see Zonghe Lai, *T-CPMB Aug 96* 644-660
Jokerst, N.M., M.A. Brooke, O. Vendier, S. Wilkinson, S. Fike, M. Lee, E. Twyford, J. Cross, B. Buchanan, and S. Wills. Thin-film multimaterial optoelectronic integrated circuits; *T-CPMB Feb 96* 97-106
Jong Jyh-Ming, see Jyh-Ming Jong, *T-CPMB Feb 96* 48-56
Jun-Wu Tao, see Salik, R., *T-CPMB Feb 96* 74-81
Jyh-Ming Jong, B. Janko, and V.K. Tripathi. Time-domain characterization and circuit modeling of a multilayer ceramic package; *T-CPMB Feb 96* 48-56

K

- Kacines, J.J.**, see Schaefer, T.M., *T-CPMB May 96* 403-416
Kaminska, B., see Rayapati, V.N., *T-CPMB Aug 96* 605-614
Kamon, M., see Miguel Silveira, L., *T-CPMB May 96* 283-288
Kang, S.G., see Song, M.K., *T-CPMB Nov 96* 758-763
Katopis, G.A., see Smith, H.H., *T-CPMB Aug 96* 503-511
Katzier, H., R. Reischl, and P. Pagnin. SPICE-models for high-pincount board connectors; *T-CPMB Feb 96* 3-6
Katzier, H., see Wolter, H., *T-CPMB Feb 96* 23-31
Kawatani, A., see Kurata, K., *T-CPMB Aug 96* 524-531
Keller, T.W., see Zabinski, P.J., *T-CPMB Feb 96* 215-224
Kelly, G., C. Lyden, W. Lawton, J. Barrett, A. Saboui, H. Pape, and H.J.B. Peters. Importance of molding compound chemical shrinkage in the stress and warpage analysis of PQFPs; *T-CPMB May 96* 296-300
Keyser, T.M., see Yung-Cheng Lee, *T-CPMB Aug 96* 540-547
Kimura, J., see Ishibashi, K., *T-CPMB Nov 96* 752-757
Kinter, R., see Siala, S., *T-CPMB Aug 96* 548-553
Kleiner, M.B., S.A. Kuhn, P. Ramm, and W. Weber. Performance improvement of the memory hierarchy of RISC-systems by application of 3-D technology; *T-CPMB Nov 96* 709-718
Kleiner, M.B., see Kuhn, S.A., *T-CPMB Nov 96* 719-727
Kobayashi, F., see Chiba, T., *T-CPMB May 96* 391-396
Koike, S., F. Simokawa, T. Matsura, and H. Takahara. New optical and electrical hybrid packaging techniques using optical waveguides for optoelectronic multichip modules; *T-CPMB Feb 96* 124-130
Koike, S., S. Matsui, and H. Takahara. Laser-diode array packaging in opto-electronic multichip modules; *T-CPMB Aug 96* 628-634
Kornegay, K.T., and K. Roy. Structured test methodologies and test economics for multichip modules; *T-CPMB Feb 96* 195-202
Kossives, D.P., see Zu, L., *T-CPMB Aug 96* 635-643
Kramer, E.J., see Stoffel, N.C., *T-CPMB May 96* 417-422
Kravitz, S.H., J.C. Word, T.M. Bauer, P.K. Seigal, and M.G. Armendariz. A passive micromachined device for alignment of arrays of single-mode fibers for hermetic photonic packaging-the CLASP concept; *T-CPMB Feb 96* 83-89
Krishnamurthy, V.B., H.S. Cole, and T. Sitnik-Nieters. Use of BCB in high frequency MCM interconnects; *T-CPMB Feb 96* 42-47
Kromann, G.B., R.D. Gerke, and Wayne Wei-Xi Huang. A hi-density C4/CBGA interconnect technology for a CMOS microprocessor; *T-CPMB Feb 96* 166-173
Krusius, J.P., see Fisher, T.S., *T-CPMB Feb 96* 255-262
Krusius, J.P., see George, A.G., *T-CPMB Nov 96* 699-708
Kuhn, S.A., see Kleiner, M.B., *T-CPMB Nov 96* 709-718

- Kuhn, S.A.**, M.B. Kleiner, P. Ramm, and W. Weber. Performance modeling of the interconnect structure of a three-dimensional integrated RISC processor/cache system; *T-CPMB Nov 96* 719-727
Kuo, S.M., *see* Schwartz, D.B., *T-CPMB Aug 96* 532-539
Kurata, K., K. Yamauchi, A. Kawatani, E. Tanaka, H. Honmou, and S. Ishikawa. A surface mount single-mode laser module using passive alignment; *T-CPMB Aug 96* 524-531
Kurzweil, K., *see* Bedouani, M., *T-CPMB May 96* 382-390
Ku Shang Jian, *see* Daping Yao, *T-CPMB Feb 96* 154-165

L

- Lai, J.K.L.**, *see* Xie, D.J., *T-CPMB Feb 96* 148-153
Lai, J.K.L., *see* Xie, D.J., *T-CPMB Aug 96* 669-678
Lai, J.K.L., *see* Xie, D.J., *T-CPMB Aug 96* 679-684
Lai Zonghe, *see* Zonghe Lai, *T-CPMB Aug 96* 644-660
Lambert, D., *see* Bedouani, M., *T-CPMB May 96* 382-390
Lanzetta, A.P., *see* Deutsch, A., *T-CPMB May 96* 331-337
Larcombe, S.P., *see* Stern, J.M., *T-CPMB Feb 96* 188-194
Laskar, J., *see* Jie Hao, *T-CPMB Aug 96* 512-517
Lau, J.H. Temperature and stress time history responses in electronic packaging; *T-CPMB Feb 96* 248-254
Lau, J.H. Solder joint reliability of flip chip and plastic ball grid array assemblies under thermal, mechanical, and vibrational conditions; *T-CPMB Nov 96* 728-735
Lau, M.Y., *see* Zu, L., *T-CPMB Aug 96* 635-643
Lawton, W., *see* Kelly, G., *T-CPMB May 96* 296-300
Lebby, M., *see* Schwartz, D.B., *T-CPMB Aug 96* 532-539
Lee, H.C., *see* Schwartz, D.B., *T-CPMB Aug 96* 532-539
Lee, H.T., *see* Song, M.K., *T-CPMB Nov 96* 758-763
Lee, M., *see* Jokerst, N.M., *T-CPMB Feb 96* 97-106
Lee, P.S., *see* Heinrich, S.M., *T-CPMB May 96* 310-319
Lee Tien-Yu Tom, *see* Tien-Yu Tom Lee, *T-CPMB Feb 96* 131-137
Lee Yung-Cheng, *see* Yung-Cheng Lee, *T-CPMB Aug 96* 540-547
Lei Guang-Tsai, *see* Jilin Tan, *T-CPMB Aug 96* 621-627
Levi, A.F.J., *see* Siala, S., *T-CPMB Aug 96* 548-553
Lewis, G., *see* Ganeshan, G.S., *T-CPMB Aug 96* 581-584
Li, H.-D., *see* Liang, T.-X., *T-CPMB May 96* 423-426
Li, Z.-F., *see* Luo, S.-P., *T-CPMB Nov 96* 770-774
Liang, T.-X., W.Z. Sun, L.-D. Wang, Y.H. Wang, and H.-D. Li. Effect of surface energies on screen printing resolution; *T-CPMB May 96* 423-426
Lin, K.-L., and S.-Y. Chang. Approaching a uniform bump height of the electroplated solder bumps on a silicon wafer; *T-CPMB Nov 96* 747-751
Lindsay, W.S., *see* Ganeshan, G.S., *T-CPMB Aug 96* 581-584
Lin Jenshan, *see* Zu, L., *T-CPMB Aug 96* 635-643
Liu Johan, *see* Zonghe Lai, *T-CPMB Aug 96* 644-660
Long Shieh Chan, *see* Schwartz, D.B., *T-CPMB Aug 96* 532-539
Loos, J.S. Leadless 432-pin package and solderless socket used in a system operating with a 622 MHz digital clock; *T-CPMB Feb 96* 174-181
Luo, S.-P., and Z.-F. Li. Extraction of the capacitance matrix of multiconductor interconnection lines for high-speed IC system design; *T-CPMB Nov 96* 770-774
Lu Yicheng, *see* Zu, L., *T-CPMB Aug 96* 635-643
Lyden, C., *see* Kelly, G., *T-CPMB May 96* 296-300
Lytle, W.H., *see* Tien-Yu Tom Lee, *T-CPMB Feb 96* 131-137

M

- Maheshwari, V.**, *see* Darnauer, J., *T-CPMB Feb 96* 263
Manoochehri, S., *see* Mottahed, B.D., *T-CPMB Feb 96* 238-247
Martens, L., *see* Sercu, S., *T-CPMB May 96* 289-295
Martin, K.P., *see* Rainer Dohle, G., *T-CPMB Feb 96* 57-63
Martin, K.P., *see* Dohle, G.R., *T-CPMB Aug 96* 575-580
Matsui, S., *see* Koike, S., *T-CPMB Aug 96* 628-634
Matsuura, T., *see* Koike, S., *T-CPMB Feb 96* 124-130
McCredie, B.D., and W.D. Becker. Modeling, measurement, and simulation of simultaneous switching noise; *T-CPMB Aug 96* 461-472
Mehr, J.F., *see* Haugsjaa, P.O., *T-CPMB Feb 96* 90-96
Menzel, W.S., *see* Strauss, G., *T-CPMB May 96* 278-282
Mertol, A. Thermal performance comparison of high pin count cavity-up enhanced plastic ball grid array (EPBGA) packages; *T-CPMB May 96* 427-443
Migom, F., *see* De pestel, G., *T-CPMB Feb 96* 116-123
Miguel Silveira, L., M. Kamon, and J. White. Efficient reduced-order modeling of frequency-dependent coupling inductances associated with 3-D interconnect structures; *T-CPMB May 96* 283-288
Moser, D.T., *see* Dautartas, M.F., *T-CPMB Aug 96* 554-561
Mosley, J., *see* Jie Hao, *T-CPMB Aug 96* 512-517

- Mottahed, B.D.**, and S. Manoochehri. Joint design methodology based on the electromagnetic shielding effectiveness capabilities; *T-CPMB Feb 96* 238-247
Mowatt, L., *see* Schaefer, T.M., *T-CPMB May 96* 403-416

N

- Nakbla, M.S.**, *see* Williamson, J.M., *T-CPMB May 96* 361-371
Nawa, K., S. Ueda, and H. Watanabe. Advanced COPNA-resin as a low temperature curing resin for high-density electronic packages; *T-CPMB Aug 96* 585-592
Negri, A.J., *see* Haugsjaa, P.O., *T-CPMB Feb 96* 90-96
Nogawa, K., *see* Uda, H., *T-CPMB Feb 96* 182-187
Norimatsu, S., *see* Tsunetsugu, H., *T-CPMB Aug 96* 569-574
Nottenburg, R.N., *see* Siala, S., *T-CPMB Aug 96* 548-553

O

- Ozaki, T.**, *see* Sakabe, Y., *T-CPMB Feb 96* 7-14

P

- Padilla, J.**, *see* Siala, S., *T-CPMB Aug 96* 548-553
Pagnin, P., *see* Katzler, H., *T-CPMB Feb 96* 3-6
Pan Guang-Wen, *see* Guang-Wen Pan, *T-CPMB Aug 96* 615-620
Pan Guang-Wen, *see* Jilin Tan, *T-CPMB Aug 96* 621-627
Pape, H., *see* Kelly, G., *T-CPMB May 96* 296-300
Park, S.S., *see* Song, M.K., *T-CPMB Nov 96* 758-763
Peters, H.J.B., *see* Kelly, G., *T-CPMB May 96* 296-300
Podebrad, O., *see* Wolter, H., *T-CPMB Feb 96* 23-31
Ponnappalli, S. Modeling and design of antennas for RF wireless systems; *T-CPMB Aug 96* 487-502
Prince, J.L., *see* Huang, C., *T-CPMB Feb 96* 15-22
Prince, J.L., *see* Abernethy, C.E., *T-CPMB Feb 96* 32-39
Prince, J.L. Foreword: Electronic performance characteristics of packaging structures [intro. to special section on contributions from the Third Topical Meeting on the Electrical Performance of Electronic Packaging]; *T-CPMB May 96* 272
Prince, J.L., *see* Secker, D.A., *T-CPMB Aug 96* 473-480
Pyun, K.E., *see* Song, M.K., *T-CPMB Nov 96* 758-763

Q

- Qi-Jun Zhang**, *see* Williamson, J.M., *T-CPMB May 96* 361-371
Quinn, W.E., *see* Yung-Cheng Lee, *T-CPMB Aug 96* 540-547

R

- Rainal, A.J.** Computing inductive noise of CMOS drivers; *T-CPMB Nov 96* 789-802
Rainer Dohle, G., J.J. Callahan, K.P. Martin, and T.J. Drabik. A new bonding technique for microwave devices; *T-CPMB Feb 96* 57-63
Ramakrishnan, V., *see* Siala, S., *T-CPMB Aug 96* 548-553
Ramirez, J., *see* Darnauer, J., *T-CPMB Feb 96* 263
Ramm, P., *see* Kleiner, M.B., *T-CPMB Nov 96* 709-718
Ramm, P., *see* Kuhn, S.A., *T-CPMB Nov 96* 719-727
Randall, B.A., *see* Schaefer, T.M., *T-CPMB May 96* 403-416
Rayapati, V.N., and B. Kaminska. Interconnect propagation delay modeling and validation for the 16-MB CMOS SRAM chip; *T-CPMB Aug 96* 605-614
Reichl, H., *see* Zankel, E., *T-CPMB Feb 96* 138-147
Reischl, R., *see* Katzler, H., *T-CPMB Feb 96* 3-6
Richter, A., *see* Jie Hao, *T-CPMB Aug 96* 512-517
Richter, H., *see* De pestel, G., *T-CPMB Feb 96* 116-123
Robinson, S.D., *see* Anigbo, F.C.J., *T-CPMB Aug 96* 562-568
Roselle, K.M., *see* Gordon, C., *T-CPMB May 96* 273-277
Roszel, L.E., *see* Schaefer, T.M., *T-CPMB May 96* 403-416
Roy, K., *see* Kornegay, K.T., *T-CPMB Feb 96* 195-202
Roy, S.K., and B.L. Avanic. A very high heat flux microchannel heat exchanger for cooling of semiconductor laser diode arrays; *T-CPMB May 96* 444-451
Rozenblit, J.W., *see* Simunic, T., *T-CPMB Nov 96* 803-812
Rubin, L.M. Application of path integrals in modeling transmission line loss; *T-CPMB Nov 96* 775-788
Ruey-Bee Wu, and Fang-Lin Chao. Flat spiral delay line design with minimum crosstalk penalty; *T-CPMB May 96* 397-402

S

- Sabou, A.**, see Kelly, G., *T-CPMB* May 96 296-300
- Saitoh, T.** Numerical stress analysis of resin cracking in LSI plastic packages under temperature cyclic loading; *T-CPMB* Aug 96 593-600
- Sakabe, Y., M. Hayashi, T. Ozaki, and J.P. Canner.** High frequency measurement of multilayer ceramic capacitors; *T-CPMB* Feb 96 7-14
- Salik, R., Jun-Wu Tao, G. Angenieux, and B. Flechet.** A rigorous method to evaluate the electrical performance of MCM interconnections in frequency and time domains; *T-CPMB* Feb 96 74-81
- Sawai, T.**, see Uda, H., *T-CPMB* Feb 96 182-187
- Schaefer, T.M., J.J. Kacines, B.A. Randall, L.E. Roszel, G.J. Fokken, D. Walter, D.J. Schwab, L. Mowatt, and B.K. Gilbert.** A chips-first multichip module implementation of passive and active test coupons utilizing Texas Instruments' high density interconnect technology; *T-CPMB* May 96 403-416
- Schroeder, S.A., see Heinrich, S.M.**, *T-CPMB* May 96 310-319
- Schwab, D.J., see Schaefer, T.M.**, *T-CPMB* May 96 403-416
- Schwartz, D.B., C.K.Y. Chun, B.M. Foley, D.H. Hartman, M. Lebby, H.C. Lee, Chan Long Shieh, S.M. Kuo, S.G. Shook, and B. Webb.** A low-cost high-performance optical interconnect; *T-CPMB* Aug 96 532-539
- Secker, D.A., and J.L. Prince.** Effects and modeling of simultaneous switching noise for BiCMOS off-chip drivers; *T-CPMB* Aug 96 473-480
- Seed, L., see Stern, J.M.**, *T-CPMB* Feb 96 188-194
- Segelken, J.M.** Foreword: Electrical package and interconnect modeling and analysis [intro. to special section on contributions from the 45th Electronic Components and Technology Conference (ECTC)]; *T-CPMB* Feb 96 2
- Seigal, P.K., see Kravitz, S.H.**, *T-CPMB* Feb 96 83-89
- Sercu, S., and L. Martens.** A new algorithm for experimental circuit modeling of interconnection structures based on causality; *T-CPMB* May 96 289-295
- Shakya, S., see Heinrich, S.M.**, *T-CPMB* May 96 310-319
- Shang Jian Ku, see Daping Yao.**, *T-CPMB* Feb 96 154-165
- Shaw, J.M., see Deutsch, A.**, *T-CPMB* May 96 331-337
- Shelley, A.J., see Stern, J.M.**, *T-CPMB* Feb 96 188-194
- Shevchuk, G.I., see Anigbo, F.C.J.**, *T-CPMB* Aug 96 562-568
- Shieh Chan Long, see Schwartz, D.B.**, *T-CPMB* Aug 96 532-539
- Shook, S.G., see Schwartz, D.B.**, *T-CPMB* Aug 96 532-539
- Siala, S., V. Ramakrishnan, M. Govindarajan, Y. Dekovic, R. Kinter, J. Padilla, A.F.J. Levi, and R.N. Nottenburg.** 622 Mb/s/channel parallel digital optical receiver array module using hybrid packaging; *T-CPMB* Aug 96 548-553
- Simokawa, F., see Koike, S.**, *T-CPMB* Feb 96 124-130
- Simunic, T., J.W. Rozenblit, and J.R. Brews.** VLSI interconnect design automation using quantitative and symbolic techniques; *T-CPMB* Nov 96 803-812
- Sitnik-Nieters, T., see Krishnamurthy, V.B.**, *T-CPMB* Feb 96 42-47
- Smith, H.H., and G.A. Katopis.** Multireflection algorithm for timed statistical coupled noise checking; *T-CPMB* Aug 96 503-511
- Smith, L.D., see Bathey, K.**, *T-CPMB* May 96 350-360
- So, A.C.K., and Y.C. Chan.** Reliability studies of surface mount solder joints - effect of Cu-Sn intermetallic compounds; *T-CPMB* Aug 96 661-668
- Song, M.K., S.G. Kang, N. Hwang, H.T. Lee, S.S. Park, and K.E. Pyun.** Laser weldability analysis of high-speed optical transmission device packaging; *T-CPMB* Nov 96 758-763
- Sparkman, A.K., see Young, B.**, *T-CPMB* Feb 96 225-229
- Stefanik, D., see Anigbo, F.C.J.**, *T-CPMB* Aug 96 562-568
- Stern, J.M., S.P. Larcombe, P.A. Ivey, L. Seed, A.J. Shelley, and N.J. Goodenough.** Design and evaluation of an epoxy three-dimensional multichip module; *T-CPMB* Feb 96 188-194
- Stoffel, N.C., M. Hsieh, E.J. Kramer, and W. Volksen.** Adhesion enhancement and lamination of polyimide films; *T-CPMB* May 96 417-422
- Strauss, G., and W.S. Menzel.** Millimeter-wave monolithic integrated circuit interconnects using electromagnetic field coupling; *T-CPMB* May 96 278-282
- Subbarayan, G., M.G. Ferrill, and S.M. DeFoster.** Reliability of metallized ceramic packages; *T-CPMB* Aug 96 685-691
- Sun, W.Z., see Liang, T.-X.**, *T-CPMB* May 96 423-426
- Surovic, C.W., see Deutsch, A.**, *T-CPMB* May 96 331-337
- Swaminathan, M., see Bathey, K.**, *T-CPMB* May 96 350-360
- Swaminathan, M., see Jie Hao.**, *T-CPMB* Aug 96 512-517
- Swirhun, S.E., see Yung-Cheng Lee.**, *T-CPMB* Aug 96 540-547

T

- Tabasky, M.J., see Haugsjaa, P.O.**, *T-CPMB* Feb 96 90-96
- Tai, K.L., see Zu, L.**, *T-CPMB* Aug 96 635-643
- Takachio, N., see Tsunetsugu, H.**, *T-CPMB* Aug 96 569-574
- Takahara, H., see Koike, S.**, *T-CPMB* Feb 96 124-130
- Takahara, H., see Koike, S.**, *T-CPMB* Aug 96 628-634
- Tan, Q., see De pestel, G.**, *T-CPMB* Feb 96 116-123

- Tanaka, E., see Kurata, K.**, *T-CPMB* Aug 96 524-531
- Tan Jilin, see Jilin Tan.**, *T-CPMB* Aug 96 621-627

- Tao Jun-Wu, see Salik, R.**, *T-CPMB* Feb 96 74-81

- Tien-Yu Tom Lee, W.H. Lytle, and B. Hileman.** Application of a CFD tool in designing a fountain plating cell for uniform bump plating of semiconductor wafers; *T-CPMB* Feb 96 131-137

- Tisdale, S.L., see Deutsch, A.**, *T-CPMB* May 96 331-337

- Tominaga, H., see Uda, H.**, *T-CPMB* Feb 96 182-187

- Tom Lee Tien-Yu, see Tien-Yu Tom Lee.**, *T-CPMB* Feb 96 131-137

- Tong Ho-Ming, see Ho-Ming Tong.**, *T-CPMB* Feb 96 203-214

- Toupikov, M., see Guang-Wen Pan.**, *T-CPMB* Aug 96 615-620

- Tripathi, V.K., see Jyh-Ming Jong.**, *T-CPMB* Feb 96 48-56

- Tsai Chi-Taou, see Chi-Taou Tsai.**, *T-CPMB* May 96 338-343

- Tsunetsugu, H., M. Hosoya, S. Norimatsu, N. Takachio, Y. Inoue, and S. Hata.** A packaging technique for an optical 90°-hybrid balanced receiver using a planar lightwave circuit; *T-CPMB* Aug 96 569-574

- Twyford, E., see Jokerst, N.M.**, *T-CPMB* Feb 96 97-106

U

- Uda, H., T. Hirai, H. Tominaga, K. Nogawa, T. Sawai, T. Higashino, and Y. Harada.** Development of ultra-compact plastic-packaged high-isolation GaAs SPDT switch; *T-CPMB* Feb 96 182-187

- Ueda, S., see Nawa, K.**, *T-CPMB* Aug 96 585-592

V

- van der Puije, P.D., see Williamson, J.M.**, *T-CPMB* May 96 361-371

- Vandewege, J., see De pestel, G.**, *T-CPMB* Feb 96 116-123

- Vemuru, S.R.** Accurate simultaneous switching noise estimation including velocity-saturation effects; *T-CPMB* May 96 344-349

- Vendier, O., see Jokerst, N.M.**, *T-CPMB* Feb 96 97-106

- Vetter, P., see De pestel, G.**, *T-CPMB* Feb 96 116-123

- Vickberg, M.E., see Zabinski, P.J.**, *T-CPMB* Feb 96 215-224

- Viebeck, A., see Deutsch, A.**, *T-CPMB* May 96 331-337

- Villain, J., see Zakel, E.**, *T-CPMB* Feb 96 138-147

- Volksen, W., see Stoffel, N.C.**, *T-CPMB* May 96 417-422

- Vrana, M., see De pestel, G.**, *T-CPMB* Feb 96 116-123

W

- Wagemans, A.G., see Baggerman, A.F.J.**, *T-CPMB* Nov 96 736-746

- Wai-Yeung Yip, see Chi-Taou Tsai.**, *T-CPMB* May 96 338-343

- Walter, D., see Schaefer, T.M.**, *T-CPMB* May 96 403-416

- Wang, L.-D., see Liang, T.-X.**, *T-CPMB* May 96 423-426

- Wang, W.-H., see Cheng, W.-H.**, *T-CPMB* Nov 96 764-769

- Wang, Y., see Heinrich, S.M.**, *T-CPMB* May 96 310-319

- Wang, Y.H., see Liang, T.-X.**, *T-CPMB* May 96 423-426

- Watanabe, H., see Nawa, K.**, *T-CPMB* Aug 96 585-592

- Wayne Wei-Xi Huang, see Kromann, G.B.**, *T-CPMB* Feb 96 166-173

- Webb, B., see Schwartz, D.B.**, *T-CPMB* Aug 96 532-539

- Weber, W., see Kleiner, M.B.**, *T-CPMB* Nov 96 709-718

- Weber, W., see Kuhn, S.A.**, *T-CPMB* Nov 96 719-727

- Weiland, T., see Wolter, H.**, *T-CPMB* Feb 96 23-31

- Wei-Xi Huang Wayne, see Kromann, G.B.**, *T-CPMB* Feb 96 166-173

- Weninger, D.V., see Zabinski, P.J.**, *T-CPMB* Feb 96 215-224

- White, J., see Miguel Silveira, L.**, *T-CPMB* May 96 283-288

- Wilkinson, S., see Jokerst, N.M.**, *T-CPMB* Feb 96 97-106

- Williamson, J.M., M.S. Nakhl, Qi-Jun Zhang, and P.D. van der Puije.** Ground noise minimization in integrated circuit packages through pin assignment optimization; *T-CPMB* May 96 361-371

- Wills, S., see Jokerst, N.M.**, *T-CPMB* Feb 96 97-106

- Wolter, H., H. Katzler, O. Podebrad, and T. Weiland.** Field-based analysis of a high pincount board connector; *T-CPMB* Feb 96 23-31

- Wondergem, J.J., see Baggerman, A.F.J.**, *T-CPMB* Nov 96 736-746

- Wong, Y.-H., see Dautartas, M.F.**, *T-CPMB* Aug 96 554-561

- Wong Yiu-Man, see Dautartas, M.F.**, *T-CPMB* Aug 96 554-561

- Woosley, A., see Ganesan, G.S.**, *T-CPMB* Aug 96 581-584

- Word, J.C., see Kravitz, S.H.**, *T-CPMB* Feb 96 83-89

- Wu Ruey-Beei, see Ruey-Beei Wu.**, *T-CPMB* May 96 397-402

X

- Xie, D.J., Y.C. Chan, and J.K.L. Lai.** An experimental approach to pore-free reflow soldering; *T-CPMB* Feb 96 148-153

- Xie, D.J., Y.C. Chan, J.K.L. Lai, and I.K. Hui.** Fatigue life estimation of surface mount solder joints; *T-CPMB* Aug 96 669-678

Xie, D.J., Y.C. Chan, J.K.L. Lai, and I.K. Hui. Fatigue life studies on defect-free solder joints fabricated from modified reflow soldering; *T-CPMB Aug 96* 679-684

Y

Yamada, M., see Chiba, T., *T-CPMB May 96* 391-396

Yamauchi, K., see Kurata, K., *T-CPMB Aug 96* 524-531

Yang, Y., see Huang, C., *T-CPMB Feb 96* 15-22

Yang, Y., and J.R. Brews. Guidelines for high-performance electronic package interconnections-a simple approach; *T-CPMB Feb 96* 230-237

Yang Yaochao, see Yaochao Yang, *T-CPMB May 96* 372-381

Yang Yaochao, see Yaochao Yang, *T-CPMB Aug 96* 481-486

Yaochao Yang, and J.R. Brews. Guidelines for high-performance electronic package interconnections approach for strong coupling; *T-CPMB May 96* 372-381

Yaochao Yang, and J.R. Brews. Design trade-offs for the last stage of an unregulated, long-channel CMOS off-chip driver with simultaneous switching noise and switching time considerations; *T-CPMB Aug 96* 481-486

Yao Daping, see Daping Yao, *T-CPMB Feb 96* 154-165

Yee, D.M., see Zabinski, P.J., *T-CPMB Feb 96* 215-224

Yicheng Lu, see Zu, L., *T-CPMB Aug 96* 635-643

Yip Wai-Yeung, see Chi-Taou Tsai, *T-CPMB May 96* 338-343

Yiu-Man Wong, see Dautartas, M.F., *T-CPMB Aug 96* 554-561

Young, B., and A.K. Sparkman. Measurement of package inductance and capacitance matrices; *T-CPMB Feb 96* 225-229

Yung-Cheng Lee, S.E. Swirhun, W.S. Fu, T.M. Keyser, J.L. Jewell, and W.E. Quinn. Thermal management of VCSEL-based optoelectronic modules; *T-CPMB Aug 96* 540-547

Z

Zabinski, P.J., M.E. Vickberg, B.K. Gilbert, P.J. Zucarelli, D.V. Weninger, T.W. Keller, and D.M. Yee. Case study: the design of a mixed-signal global positioning system receiver using multichip module packaging; *T-CPMB Feb 96* 215-224

Zakel, E., J. Villain, and H. Reichl. Reliability and Au-concentration in OLB solder fillets of TAB-devices having a 75 μm pitch; *T-CPMB Feb 96* 138-147

Zhang Qi-Jun, see Williamson, J.M., *T-CPMB May 96* 361-371

Zonghe Lai, and Johan Liu. Anisotropically conductive adhesive flip-chip bonding on rigid and flexible printed circuit substrates; *T-CPMB Aug 96* 644-660

Zu, L., Yicheng Lu, R.C. Frye, M.Y. Lau, S.-C.S. Chen, D.P. Kossives, Jenshan Lin, and K.L. Tai. High Q-factor inductors integrated on MCM Si substrates; *T-CPMB Aug 96* 635-643

Zucarelli, P.J., see Zabinski, P.J., *T-CPMB Feb 96* 215-224

SUBJECT INDEX**A****Admittance measurement**

large pin count electronic packages, capacitance/conductance/resist./inductance matrices. **Young, B.**, +, *T-CPMB Feb 96* 225-229

Aging

anisotropically conductive adhesive flip-chip bonding, expt. study. **Zonghe Lai**, +, *T-CPMB Aug 96* 644-660

TAB-OLB contacts, 75 μm pitch, long-term reliab. **Zakel, E.**, +, *T-CPMB Feb 96* 138-147

Aluminum materials/devices

metallized ceramic packages, reliab. assess. **Subbarayan, G.**, +, *T-CPMB Aug 96* 685-691

Analog integrated circuits; cf. **Microwave integrated circuits**; Mixed analog-digital integrated circuits; UHF integrated circuits
Anisotropic media

anisotropic conductive film with arrayed conductive particles. **Ishibashi, K.**, +, *T-CPMB Nov 96* 752-757

Annealing

fully imidized polyimide films, adhesion enhancement and lamination, packaging appls. **Stoffel, N.C.**, +, *T-CPMB May 96* 417-422

Antennas

contributions from the 4th IEEE Topical Meeting on Electrical Performance of Electronic Packaging (special section). *T-CPMB Aug 96* 460-522

Antennas; cf. **Mobile antennas****Antenna theory**

RF wireless systs., antenna modeling and design. **Ponnappalli, S.**, *T-CPMB Aug 96* 487-502

Arrays; cf. **Logic arrays**; Nonuniformly spaced arrays; Optical arrays

Assembly systems

anisotropically conductive adhesive flip-chip bonding, expt. study. **Zonghe Lai**, +, *T-CPMB Aug 96* 644-660

surface mount single-mode LD module, pass. alignment. **Kurata, K.**, +, *T-CPMB Aug 96* 524-531

ATE (automatic test equipment); cf. **Automatic testing**

Automatic testing

struct. test methodologies and test economics for MCM. **Kornegay, K.T.**, +, *T-CPMB Feb 96* 195-202

Automation; cf. **Automatic testing**; **Design automation**

B

BiCMOS integrated circuits

off-chip driver, simultaneous switching noise. **Secker, D.A.**, +, *T-CPMB Aug 96* 473-480

Bipolar digital integrated circuits; cf. **BiCMOS integrated circuits**; Emitter coupled logic; Transistor-transistor logic

Bonding

anisotropic conductive film with arrayed conductive particles. **Ishibashi, K.**, +, *T-CPMB Nov 96* 752-757

Bonding; cf. **Integrated circuit bonding**; Laser weldings; Lead bonding; Semiconductor device bonding; Soldering

Boundary scan testing

struct. test methodologies and test economics for MCM. **Kornegay, K.T.**, +, *T-CPMB Feb 96* 195-202

Business economics; cf. **Manufacturing economics**

C

Cache memories

perform. modeling of interconnect struct. of 3D integrated RISC processor/cache syst. **Kuhn, S.A.**, +, *T-CPMB Nov 96* 719-727

CAD (computer aided design); cf. **Design automation**

Calculus; cf. **Integration (math.)**

Capacitance

extraction of capacitance matrix of multiconductor interconnection lines for high-speed IC syst. design. **Luo, S.-P.**, +, *T-CPMB Nov 96* 770-774

IC interconnect, multilayer dielec., crossover capacitance. **Guang-Wen Pan**, +, *T-CPMB Aug 96* 615-620

Capacitance measurement

integral decoupling capacitors, time/freq. domain anal. **Goetz, M.P.**, *T-CPMB Aug 96* 518-522

large pin count electronic packages, capacitance/conductance/resist./inductance matrices. **Young, B.**, +, *T-CPMB Feb 96* 225-229

Capacitors

integral decoupling capacitors, time/freq. domain anal. **Goetz, M.P.**, *T-CPMB Aug 96* 518-522

Capacitors; cf. **Ceramic capacitors**

Ceramic capacitors

MLC capacitor, HF meas. **Sakabe, Y.**, +, *T-CPMB Feb 96* 7-14

Ceramic materials/devices

glass ceramic multichip carriers, press. sintering. **Ho-Ming Tong**, +, *T-CPMB Feb 96* 203-214

metallized ceramic packages, reliab. assess. **Subbarayan, G.**, +, *T-CPMB Aug 96* 685-691

polyimide-Cu thin-film multilayer interconnects on ceramic substr. **Bendouani, M.**, +, *T-CPMB May 96* 382-390

Ceramic materials/devices; cf. **Ceramic capacitors**

Circuit analysis; cf. **Circuit transient analysis**

Circuit boards; cf. **Layout of circuit boards**; **Printed circuits**

Circuit modeling

appl. of path integrals in modeling transm. line loss. **Rubin, L.M.**, *T-CPMB Nov 96* 775-788

two-port interconnection struct., cct. modeling, causality. **Sercu, S.**, +, *T-CPMB May 96* 289-295

Circuit modeling; cf. **Integrated circuit modeling**

Circuit noise

timed stat. coupled noise checking, multirefl. algm. **Smith, H.H.**, +, *T-CPMB Aug 96* 503-511

Circuit noise; cf. **Integrated circuit noise**

Circuit optimization

IC packages, pin assignment, ground noise minimization. **Williamson, J.M.**, +, *T-CPMB May 96* 361-371

Circuit optimization; cf. **Layout of circuit boards**

Circuit reliability

defect-free solder joints, reflow soldering fab., fatigue life study. **Xie, D.J.**, +, *T-CPMB Aug 96* 679-684

+ Check author entry for coauthors

† Check author entry for subsequent corrections/comments

- surface mount solder joints, fatigue life estim. *Xie, D.J.*, +, *T-CPMB Aug 96* 669-678
- TAB-OLB contacts, 75 µm pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147
- Circuit reliability;** cf. Integrated circuit reliability
- Circuits;** cf. Coupling circuits; Distributed parameter circuits; Equivalent circuits; Feedback circuits; Integrated circuits; Logic circuits; Lossy circuits; Multiport circuits; Printed circuits; Programmable circuits
- Circuit simulation**
- CMOS chip, simultaneous switching noise. *McCredie, B.D.*, +, *T-CPMB Aug 96* 461-472
- contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *Celik, M.*, +, *T-CPMB Aug 96* 692
- GaAs high-isolation SPDT switch, ultra-compact plastic-packaged develop. *Uda, H.*, +, *T-CPMB Feb 96* 182-187
- lossy packaging interconnects, transient simul., moment-matching. *Celik, M.*, +, *T-CPMB Feb 96* 64-73
- timed stat. coupled noise checking, multirefl. algm. *Smith, H.H.*, +, *T-CPMB Aug 96* 503-511
- Circuit transient analysis**
- contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *Celik, M.*, +, *T-CPMB Aug 96* 692
- lossy packaging interconnects, transient simul., moment-matching. *Celik, M.*, +, *T-CPMB Feb 96* 64-73
- CMOS digital integrated circuits**
- µP, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173
- CMOS digital integrated circuits;** cf. CMOS memory integrated circuits
- CMOSFETs;** cf. CMOS..
- CMOS integrated circuit noise**
- computing inductive noise of CMOS drivers. *Rainal, A.J.*, *T-CPMB Nov 96* 789-802
- CMOS integrated circuits**
- computing inductive noise of CMOS drivers. *Rainal, A.J.*, *T-CPMB Nov 96* 789-802
- multilayer substr., transm. line, full wave anal. *Jilin Tan*, +, *T-CPMB Aug 96* 621-627
- off-chip driver, design, simultaneous switching noise. *Yaochao Yang*, +, *T-CPMB Aug 96* 481-486
- package interconnections, strong coupling lines. *Yaochao Yang*, +, *T-CPMB May 96* 372-381
- simultaneous switching noise. *McCredie, B.D.*, +, *T-CPMB Aug 96* 461-472
- simultaneous switching noise, vel. saturation. *Vemuru, S.R.*, *T-CPMB May 96* 344-349
- thin-film multimaterial OEICs, interconnect appls. *Jokerst, N.M.*, +, *T-CPMB Feb 96* 97-106
- CMOS integrated circuits;** cf. BiCMOS integrated circuits; CMOS digital integrated circuits
- CMOS memory integrated circuits**
- SRAM chip, interconnect propag. delay model. *Rayapati, V.N.*, +, *T-CPMB Aug 96* 605-614
- Coatings**
- ball grid array packages, PCB finish, reliab. and wettability. *Bradley, E.*, +, *T-CPMB May 96* 320-330
- Communication equipment;** cf. Optical communication equipment
- Communication standards;** cf. FDDI
- Communication systems;** cf. Data communication; Digital communication
- Complementary MOS;** cf. CMOS integrated circuits
- Computer aided design;** cf. Design automation
- Computer architecture;** cf. Parallel architectures
- Computer communication;** cf. Data communication
- Computer networks;** cf. Local area networks
- Conducting films**
- anisotropic conductive film with arrayed conductive particles. *Ishibashi, K.*, +, *T-CPMB Nov 96* 752-757
- Connectors**
- board connector, high pincount, field-based anal. *Wolter, H.*, +, *T-CPMB Feb 96* 23-31
- board connectors, high-pincount, SPICE-models. *Katzier, H.*, +, *T-CPMB Feb 96* 3-6
- contributions from 45th Electronic Components and Technology Conference (ECTC), (special section). *T-CPMB Feb 96* 1-39
- leadless MCM-D electronic package, 432-pin land-grid I/O array. *Loos, J.S.*, *T-CPMB Feb 96* 174-181
- Connectors;** cf. Optical fiber connecting
- Contact mechanical factors**
- TAB-OLB contacts, 75 µm pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147
- Control systems;** cf. Reduced order systems
- Cooling**
- convectively cooled substr., transient thermal response. *Fisher, T.S.*, +, *T-CPMB Feb 96* 255-262
- Cu/Sn-Pb solder joints, interfacial fatigue-crack growth, cooling rate effect. *Daping Yao*, +, *T-CPMB Feb 96* 154-165
- diode laser arrays, cooling, microchannel heat exchanger. *Roy, S.K.*, +, *T-CPMB May 96* 444-451
- leadless MCM-D electronic package, 432-pin land-grid I/O array. *Loos, J.S.*, *T-CPMB Feb 96* 174-181
- porphritic heat sink paste, thermal cond. meas., MCM. *Artus, R.G.C.*, *T-CPMB Aug 96* 601-604
- VCSEL-based optoelectronic modules, thermal mgt. *Yung-Cheng Lee*, +, *T-CPMB Aug 96* 540-547
- Copper materials/devices**
- Cu/Sn-Pb solder joints, interfacial fatigue-crack growth, cooling rate effect. *Daping Yao*, +, *T-CPMB Feb 96* 154-165
- polyimide-Cu thin-film multilayer interconnects on ceramic substr. *Bedouani, M.*, +, *T-CPMB May 96* 382-390
- surface mount solder joints reliab. study, effect of Cu-Sn alloys. *So, A.C.K.*, +, *T-CPMB Aug 96* 661-668
- TAB-OLB contacts, 75 µm pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147
- Corrugated waveguides;** cf. Distributed feedback lasers
- Coupled transmission lines**
- multiconductor coupled transm. lines, inter-chip interconnects, crosstalk estim. *Gordon, C.*, +, *T-CPMB May 96* 273-277
- Couplers;** cf. Optical couplers
- Coupling;** cf. Electromagnetic coupling
- Coupling circuits**
- timed stat. coupled noise checking, multirefl. algm. *Smith, H.H.*, +, *T-CPMB Aug 96* 503-511
- Crosstalk**
- board connector, high pincount, field-based anal. *Wolter, H.*, +, *T-CPMB Feb 96* 23-31
- board connectors, high-pincount, SPICE-models. *Katzier, H.*, +, *T-CPMB Feb 96* 3-6
- chip-first MCM implement., pass./act. test coupons, HDI. *Schaefer, T.M.*, +, *T-CPMB May 96* 403-416
- flat spiral delay line design, min. crosstalk penalty. *Ruey-Beei Wu*, +, *T-CPMB May 96* 397-402
- high-dens. electronic package interconnections, design guidelines. *Yang, Y.*, +, *T-CPMB Feb 96* 230-237
- IC package interconnections, strong coupling lines. *Yaochao Yang*, +, *T-CPMB May 96* 372-381
- multiconductor coupled transm. lines, inter-chip interconnects, crosstalk estim. *Gordon, C.*, +, *T-CPMB May 96* 273-277
- Crosstalk;** cf. Optical crosstalk
- Current**
- semicond. wafers, uniform bump plating, fountain plating cell. *Tien-Yu Tom Lee*, +, *T-CPMB Feb 96* 131-137

D**Data communication**

self-aligned MCM-D based opt. data links, opt. perform. *Dautartas, M.F.*, +, *T-CPMB Aug 96* 554-561

Data transmission; cf. Data communication**Deconvolution**

MLC package, time-domain meas. and cct. modeling. *Jyh-Ming Jong*, +, *T-CPMB Feb 96* 48-56

Decoupling of systems

integral decoupling capacitors, time/freq. domain anal. *Goetz, M.P.*, *T-CPMB Aug 96* 518-522

Delay effects

CMOS SRAM chip, interconnect propag. delay model. *Rayapati, V.N.*, +, *T-CPMB Aug 96* 605-614

struct. test methodologies and test economics for MCM. *Kornegay, K.T.*, +, *T-CPMB Feb 96* 195-202

Delay estimation

multiconductor coupled transm. lines, inter-chip interconnects, crosstalk estim. *Gordon, C.*, +, *T-CPMB May 96* 273-277

Delay lines

flat spiral delay line design, min. crosstalk penalty. *Ruey-Beei Wu*, +, *T-CPMB May 96* 397-402

Design automation

GaAs high-isolation SPDT switch, ultra-compact plastic-packaged develop. *Uda, H.*, +, *T-CPMB Feb 96* 182-187

IC packages, pin assignment, ground noise minimization. *Williamson, J.M.*, +, *T-CPMB May 96* 361-371

leadframe packages, simultaneous switching noise design algm. *Huang, C.*, +, *T-CPMB Feb 96* 15-22

VLSI interconnect design automation using quantitat. and symbolic techs. *Simunic, T.*, +, *T-CPMB Nov 96* 803-812

Design automation software; cf. SPICE**Design for testability**

struct. test methodologies and test economics for MCM. *Kornegay, K.T.*, +, *T-CPMB Feb 96* 195-202

Design methodology; cf. Design automation**Dielectric films;** cf. Plastic films**Dielectric losses**

CMOS multilayer substr., transm. line, full wave anal. *Jilin Tan*, +, *T-CPMB Aug 96* 621-627

- cyanate ester PCB material, dielec. const. and loss. *Deutsch, A.*, +, *T-CPMB May 96* 331-337
 MCM, HF interconnects, BCB adhesive. *Krishnamurthy, V.B.*, +, *T-CPMB Feb 96* 42-47
Dielectric materials/devices
 cyanate ester PCB material, dielec. const. and loss. *Deutsch, A.*, +, *T-CPMB May 96* 331-337
Dielectric materials/devices; cf. Capacitors; Plastic materials/devices
Dielectric measurements; cf. Capacitance measurement
Dielectric waveguides; cf. Optical waveguides
Diffusion processes
 AuSn low temp. bonding of epitaxial lift off devices, optoelectronic ICs. *Dohle, G.R.*, +, *T-CPMB Aug 96* 575-580
 TAB-OLB contacts, 75 µm pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147
Digital communication
 parallel digital opt. receiver array module, hybrid packaging, 622 Mb/s/channel. *Siala, S.*, +, *T-CPMB Aug 96* 548-553
Digital integrated circuits
 chips-first MCM implement., pass./act. test coupons, HDI. *Schaefer, T.M.*, +, *T-CPMB May 96* 403-416
Digital integrated circuits; cf. Mixed analog-digital integrated circuits
Digital modulation/demodulation; cf. Phase shift keying
Digital transmission; cf. Digital communication
Diode lasers; cf. Semiconductor lasers
Discontinuities; cf. Transmission line discontinuities
Dissipative circuits; cf. Lossy circuits
Distortion; cf. Delay effects
Distributed computing; cf. Local area networks
Distributed feedback lasers
 laser weldability anal. of high-speed opt. transm. device packaging. *Song, M.K.*, +, *T-CPMB Nov 96* 758-763
Distributed parameter circuits
 appl. of path integrals in modeling transm. line loss. *Rubin, L.M.*, *T-CPMB Nov 96* 775-788
 timed stat. coupled noise checking, multirefl. algm. *Smith, H.H.*, +, *T-CPMB Aug 96* 503-511
- E**
- ECL; cf. Emitter coupled logic**
Electrical equipment enclosures
 enclosures, joint design methodology, EM shielding effectiveness capabilities. *Mottahed, B.D.*, +, *T-CPMB Feb 96* 238-247
Electrical Performance of Electronic Packaging, 4th (1995) IEEE Topical Meeting on
 contributions (special section). *T-CPMB Aug 96* 460-522
Electrical Performance of Electronic Packaging, IEEE Third Topical Meeting on the
 contributions (special section). *T-CPMB May 96* 272-295
Electric field effects; cf. Electrooptic materials/devices
Electric variables; cf. Capacitance; Current; Permittivity
Electric variables measurement; cf. Admittance measurement; Capacitance measurement; Inductance measurement; Resistance measurement; Transmission line measurements
Electroabsorption; cf. Electrooptic materials/devices
Electromagnetic analysis
 3D interconnect struct., freq.-depend. coupling inductances, reduced-order modeling. *Miguel Silveira, L.*, +, *T-CPMB May 96* 283-288
Electromagnetic conductive interference
 timed stat. coupled noise checking, multirefl. algm. *Smith, H.H.*, +, *T-CPMB Aug 96* 503-511
Electromagnetic coupling
 3D interconnect struct., freq.-depend. coupling inductances, reduced-order modeling. *Miguel Silveira, L.*, +, *T-CPMB May 96* 283-288
 MIMIC interconnects, EM field coupling. *Strauss, G.*, +, *T-CPMB May 96* 278-282
 timed stat. coupled noise checking, multirefl. algm. *Smith, H.H.*, +, *T-CPMB Aug 96* 503-511
Electromagnetic coupling; cf. Optical coupling
Electromagnetic inductive interference
 computing inductive noise of CMOS drivers. *Rainal, A.J.*, *T-CPMB Nov 96* 789-802
Electromagnetic interference
 enclosures, joint design methodology, EM shielding effectiveness capabilities. *Mottahed, B.D.*, +, *T-CPMB Feb 96* 238-247
Electromagnetic interference; cf. Crosstalk; Electromagnetic conductive interference
Electromagnetic measurements; cf. Microwave measurements
Electromagnetic noise; cf. Electromagnetic interference
Electromagnetic shielding
 enclosures, joint design methodology, EM shielding effectiveness capabilities. *Mottahed, B.D.*, +, *T-CPMB Feb 96* 238-247
- Electromagnetic transient analysis; cf. Switching transients**
Electromechanical devices; cf. Microelectromechanical devices
Electronic Components and Manufacturing Technology Conference, 45th
 contributions (special section). *T-CPMB May 96* 296-330
Electronic Components and Technology Conference, 45th (1995)
 contributions on optoelectronic packaging (special section). *T-CPMB Aug 96* 523-580
 contributions (special section). *T-CPMB Feb 96* 1-39
Electron microscopy
 anisotropically conductive adhesive flip-chip bonding, expt. study. *Zonghe Lai*, +, *T-CPMB Aug 96* 644-660
 AuSn low temp. bonding of epitaxial lift off devices, optoelectronic ICs. *Dohle, G.R.*, +, *T-CPMB Aug 96* 575-580
 surface mount solder joints reliab. study, effect of Cu-Sn alloys. *So, A.C.K.*, +, *T-CPMB Aug 96* 661-668
Electrooptic materials/devices
 multichannel opt. modules compatible, fiber-in-board technol. *De pestel, G.*, +, *T-CPMB Feb 96* 116-123
Electrooptic materials/devices; cf. Self-electrooptic-effect devices
EMI; cf. Electromagnetic interference
Emitter coupled logic
 leadless MCM-D electronic package, 432-pin land-grid I/O array. *Loos, J.S.*, *T-CPMB Feb 96* 174-181
Encapsulation
 PQFPs, molding cpd. chem. shrinkage in stress and warpage anal. *Kelly, G.*, +, *T-CPMB May 96* 296-300
Enclosures; cf. Electrical equipment enclosures
Environmental testing
 anisotropically conductive adhesive flip-chip bonding, expt. study. *Zonghe Lai*, +, *T-CPMB Aug 96* 644-660
 metallized ceramic packages, reliab. assess. *Subbarayan, G.*, +, *T-CPMB Aug 96* 685-691
Epoxy resin materials/devices
 epoxy 3D MCM, Design and eval. for portable video equip. *Stern, J.M.*, +, *T-CPMB Feb 96* 188-194
Equations; cf. Integral equations
Equivalent circuits
 contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *Celik, M.*, +, *T-CPMB Aug 96* 692
 IC interconnect, multilayer dielec., crossover capacitance. *Guang-Wen Pan*, +, *T-CPMB Aug 96* 615-620
 lossy packaging interconnects, transient simul., moment-matching. *Celik, M.*, +, *T-CPMB Feb 96* 64-73
 microelectronic interconnects, transm. line params. meas. *Abernethy, C.E.*, +, *T-CPMB Feb 96* 32-39
 MLC capacitor, HF meas. *Sakabe, Y.*, +, *T-CPMB Feb 96* 7-14
 MLC package, time-domain meas. and ect. modeling. *Jyh-Ming Jong*, +, *T-CPMB Feb 96* 48-56
 very small peripheral array package, charactn. *Jie Hao*, +, *T-CPMB Aug 96* 512-517
Estimation; cf. Delay estimation
Etching; cf. Sputter etching
- F**
- Fabrication; cf. Bonding; Integrated circuit fabrication; Printed circuit fabrication**
Failure analysis
 anisotropically conductive adhesive flip-chip bonding, expt. study. *Zonghe Lai*, +, *T-CPMB Aug 96* 644-660
Failure analysis; cf. Reliability
FDDI
 high speed opt. transceiver, two-step overmold packaging technol., FDDI and FCLANs. *Anigbo, F.C.J.*, +, *T-CPMB Aug 96* 562-568
Feedback circuits
 BiCMOS off-chip driver, simultaneous switching noise. *Secker, D.A.*, +, *T-CPMB Aug 96* 473-480
Feedback lasers; cf. Distributed feedback lasers
FET integrated circuits; cf. MESFET integrated circuits
Fiber Distributed Data Interface; cf. FDDI
Fiber optics; cf. Optical fibers
Films; cf. Conducting films
Finite difference methods
 IC interconnect, multilayer dielec., crossover capacitance. *Guang-Wen Pan*, +, *T-CPMB Aug 96* 615-620
Finite element methods
 electronic packaging, temp. and stress time hist. responses. *Lau, J.H.*, *T-CPMB Feb 96* 248-254
 EPBGAs packages, cavity-up, thermal perform. *Mertol, A.*, *T-CPMB May 96* 427-443
 LSI plastic packages, resin cracking, temp. cyclic loading, stress anal. *Saitoh, T.*, *T-CPMB Aug 96* 593-600
 metallized ceramic packages, reliab. assess. *Subbarayan, G.*, +, *T-CPMB Aug 96* 685-691

PQFPs, molding cpd. chem. shrinkage in stress and warpage anal. *Kelly, G., +, T-CPMB May 96 296-300*

Fluid flow

semicond. wafers, uniform bump plating, fountain plating cell. *Tien-Yu Tom Lee, +, T-CPMB Feb 96 131-137*

Focusing; cf. Lenses**Frequency domain analysis**

integral decoupling capacitors, time/freq. domain anal. *Goetz, M.P., T-CPMB Aug 96 518-522*

MCM interconnections, freq. and time domain anal. *Salik, R., +, T-CPMB Feb 96 74-81*

packages, inductance matrix meas. *Chi-Taou Tsai, +, T-CPMB May 96 338-343*

Functions; cf. Transfer functions**G****Galerkin's method; cf. Moment methods****Gallium materials/devices**

GaAs high-isolation SPDT switch, ultra-compact plastic-packaged develop. *Uda, H., +, T-CPMB Feb 96 182-187*

Global Positioning System

mixed-sig. GPS receiver, MCM packaging. *Zabinski, P.J., +, T-CPMB Feb 96 215-224*

Gold materials/devices

AuSn alloy bonding tech., microwave devices. *Rainer Dohle, G., +, T-CPMB Feb 96 57-63*

AuSn low temp. bonding of epitaxial lift off devices, optoelectronic ICs. *Dohle, G.R., +, T-CPMB Aug 96 575-580*

TAB-OLB contacts, 75 µm pitch, long-term reliab. *Zakel, E., +, T-CPMB Feb 96 138-147*

GPS; cf. Global Positioning System**H****Heat treatment; cf. Annealing****Hierarchical memories; cf. Memory hierarchies****High-speed circuits/devices**

appl. of path integrals in modeling transm. line loss. *Rubin, L.M., T-CPMB Nov 96 775-788*

integral decoupling capacitors, time/freq. domain anal. *Goetz, M.P., T-CPMB Aug 96 518-522*

laser weldability anal. of high-speed opt. transm. device packaging. *Song, M.K., +, T-CPMB Nov 96 758-763*

High-speed circuits/devices; cf. High-speed integrated circuits**High-speed integrated circuits**

CMOS SRAM chip, interconnect propag. delay model. *Rayapati, V.N., +, T-CPMB Aug 96 605-614*

extraction of capacitance matrix of multiconductor interconnection lines for high-speed IC syst. design. *Luo, S.-P., +, T-CPMB Nov 96 770-774*
leadless MCM-D electronic package, 432-pin land-grid I/O array. *Loos, J.S., T-CPMB Feb 96 174-181*

MLC package, time-domain meas. and cct. modeling. *Jyh-Ming Jong, +, T-CPMB Feb 96 48-56*

Homodyne detection

90°-hybrid bal. opt. receiver using planar lightwave cct., packaging tech. *Tsunetsugu, H., +, T-CPMB Aug 96 569-574*

Humidity

anisotropically conductive adhesive flip-chip bonding, expt. study. *Zonghe Lai, +, T-CPMB Aug 96 644-660*

Hybrid junctions

90°-hybrid bal. opt. receiver using planar lightwave cct., packaging tech. *Tsunetsugu, H., +, T-CPMB Aug 96 569-574*

I**Image processing; cf. Optical image processing****Image sensors; cf. TV image sensors****Imaging/mapping; cf. Microscopy; Radiography****Indium materials/devices**

semicond. wafers, uniform bump plating, fountain plating cell. *Tien-Yu Tom Lee, +, T-CPMB Feb 96 131-137*

Inductance measurement

large pin count electronic packages, capacitance/conductance/resist./in-

ductance matrices. *Young, B., +, T-CPMB Feb 96 225-229*
packages, inductance matrix meas. *Chi-Taou Tsai, +, T-CPMB May 96 338-343*

Inductors; cf. Thin film inductors**Infrared spectroscopy**

COPNA-resin, low temp. curing resin for high-dens. electronic packages. *Nawa, K., +, T-CPMB Aug 96 585-592*

Injection lasers; cf. Semiconductor lasers**Integral equations**

appl. of path integrals in modeling transm. line loss. *Rubin, L.M., T-CPMB Nov 96 775-788*

Integral equations; cf. Moment methods**Integrated circuit bonding**

anisotropically conductive adhesive flip-chip bonding, expt. study. *Zonghe Lai, +, T-CPMB Aug 96 644-660*

AuSn low temp. bonding of epitaxial lift off devices, optoelectronic ICs. *Dohle, G.R., +, T-CPMB Aug 96 575-580*

Cu/Sn-Pb solder joints, interfacial fatigue-crack growth, cooling rate ef-

fect. *Daping Yao, +, T-CPMB Feb 96 154-165*

fountain plating cell, uniform bump plating. *Tien-Yu Tom Lee, +, T-CPMB Feb 96 131-137*

low-cost flip-chip on board. *Baggerman, A.F.J., +, T-CPMB Nov 96 736-746*

MCM, HF interconnects, BCB adhesive. *Krishnamurthy, V.B., +, T-CPMB Feb 96 42-47*

optoelectronic MCMs, opt./elec. hybrid packaging techs. *Koike, S., +, T-CPMB Feb 96 124-130*

solder joint reliab. of flip chip and plastic ball grid array assemblies under thermal, mech., and vibr. conditions. *Lau, J.H., T-CPMB Nov 96 728-735*

Integrated circuit bonding; cf. Thick film circuit bonding; Thin film circuit bonding**Integrated circuit design**

CMOS off-chip driver, design, simultaneous switching noise. *Yaochao Yang, +, T-CPMB Aug 96 481-486*

mixed-sig. GPS receiver, MCM packaging. *Zabinski, P.J., +, T-CPMB Feb 96 215-224*

package interconnections, strong coupling lines. *Yaochao Yang, +, T-CPMB May 96 372-381*

packages, pin assignment, ground noise minimization. *Williamson, J.M., +, T-CPMB May 96 361-371*

Integrated circuit design; cf. Layout of integrated circuits**Integrated circuit fabrication**

GaAs high-isolation SPDT switch, ultra-compact plastic-packaged develop. *Uda, H., +, T-CPMB Feb 96 182-187*

Integrated circuit fabrication; cf. Integrated circuit bonding; Integrated circuit packaging; Thick film circuit fabrication**Integrated circuit interconnections**

3D interconnect struct., freq.-depend. coupling inductances, reduced-order modeling. *Miguel Silveira, L., +, T-CPMB May 96 283-288*

chips-first MCM implement., pass./act. test coupons, HDI. *Schaefer, T.M., +, T-CPMB May 96 403-416*

CMOS multilayer substr., transm. line, full wave anal. *Jilin Tan, +, T-CPMB Aug 96 621-627*

CMOS µP, hi-dens. C4/CBGa interconnect technol. *Kromann, G.B., +, T-CPMB Feb 96 166-173*

CMOS SRAM chip, interconnect propag. delay model. *Rayapati, V.N., +, T-CPMB Aug 96 605-614*

contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *Celik, M., +, T-CPMB Aug 96 692*

extraction of capacitance matrix of multiconductor interconnection lines for high-speed IC syst. design. *Luo, S.-P., +, T-CPMB Nov 96 770-774*

flat spiral delay line design, min. crosstalk penalty. *Ruey-Beei Wu, +, T-CPMB May 96 397-402*

high-dens. electronic package interconnections, design guidelines. *Yang, Y., +, T-CPMB Feb 96 230-237*

lossy packaging interconnects, transient simul., moment-matching. *Celik, M., +, T-CPMB Feb 96 64-73*

low-cost flip-chip on board. *Baggerman, A.F.J., +, T-CPMB Nov 96 736-746*

MCM, HF interconnects, BCB adhesive. *Krishnamurthy, V.B., +, T-CPMB Feb 96 42-47*

MCM interconnections, freq. and time domain anal. *Salik, R., +, T-CPMB Feb 96 74-81*

MIMIC interconnects, EM field coupling. *Strauss, G., +, T-CPMB May 96 278-282*

MLC package, time-domain meas. and cct. modeling. *Jyh-Ming Jong, +, T-CPMB Feb 96 48-56*

multiconductor coupled transm. lines, inter-chip interconnects, crosstalk estim. *Gordon, C., +, T-CPMB May 96 273-277*

multilayer dielec., crossover capacitance. *Guang-Wen Pan, +, T-CPMB Aug 96 615-620*

package interconnections, strong coupling lines. *Yaochao Yang, +, T-CPMB May 96 372-381*

packaging alternatives to large Si chips, tiled Si on MCM and PWB substrs. *George, A.G., +, T-CPMB Nov 96 699-708*

perform. modeling of interconnect struct. of 3D integrated RISC proces-

sor/cache syst. *Kuhn, S.A., +, T-CPMB Nov 96 719-727*

sig. pin dens. limitations on wiring boards. *Chiba, T., +, T-CPMB May 96 391-396*

transm. line params. meas. *Abernethy, C.E., +, T-CPMB Feb 96 32-39*

two-port interconnection struct., cct. modeling, causality. *Sercu, S., +, T-CPMB May 96 289-295*

VLSI interconnect design automation using quantitat. and symbolic techs. *Simunic, T., +, T-CPMB Nov 96 803-812*

Integrated circuit interconnections; cf. Thin film circuit interconnections

Integrated circuit manufacture; cf. Integrated circuit fabrication

Integrated circuit measurements

interconnections, transm. line params. meas. *Abernethy, C.E.*, +, *T-CPMB Feb 96* 32-39

MLC package, time-domain meas. and cct. modeling. *Jyh-Ming Jong*, +, *T-CPMB Feb 96* 48-56

Integrated circuit mechanical factors

CMOS µP, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173

Cu/Sn-Pb solder joints, interfacial fatigue-crack growth, cooling rate effect. *Daping Yao*, +, *T-CPMB Feb 96* 154-165

PQFPs, molding cpd. chem. shrinkage in stress and warpage anal. *Kelly, G.*, +, *T-CPMB May 96* 296-300

solder joint reliab. of flip chip and plastic ball grid array assemblies under thermal, mech., and vibr. conditions. *Lau, J.H.*, *T-CPMB Nov 96* 728-735

tapeless lead-on-chip packages, cracking, adhesive effects. *Amagai, M.*, *T-CPMB May 96* 301-309

Integrated circuit metallization; cf. Integrated circuit interconnections;

Thin film circuit interconnections

Integrated circuit modeling

BiCMOS off-chip driver, simultaneous switching noise. *Secker, D.A.*, +, *T-CPMB Aug 96* 473-480

CMOS chip, simultaneous switching noise. *McCredie, B.D.*, +, *T-CPMB Aug 96* 461-472

CMOS multilayer substr., transm. line, full wave anal. *Jilin Tan*, +, *T-CPMB Aug 96* 621-627

CMOS SRAM chip, interconnect propag. delay model. *Rayapati, V.N.*, +, *T-CPMB Aug 96* 605-614

interconnect, multilayer dielec., crossover capacitance. *Guang-Wen Pan*, +, *T-CPMB Aug 96* 615-620

MLC package, time-domain meas. and cct. modeling. *Jyh-Ming Jong*, +, *T-CPMB Feb 96* 48-56

packages, pin assignment, ground noise minimization. *Williamson, J.M.*, +, *T-CPMB May 96* 361-371

Integrated circuit noise

BiCMOS off-chip driver, simultaneous switching noise. *Secker, D.A.*, +, *T-CPMB Aug 96* 473-480

CMOS ccts., simultaneous switching noise, vel. saturation. *Vemuru, S.R.*, *T-CPMB May 96* 344-349

CMOS chip, simultaneous switching noise. *McCredie, B.D.*, +, *T-CPMB Aug 96* 461-472

CMOS off-chip driver, design, simultaneous switching noise. *Yaochao Yang*, +, *T-CPMB Aug 96* 481-486

computing inductive noise of CMOS drivers. *Rainal, A.J.*, *T-CPMB Nov 96* 789-802

leadframe packages, simultaneous switching noise design algm. *Huang, C.*, +, *T-CPMB Feb 96* 15-22

package interconnections, strong coupling lines. *Yaochao Yang*, +, *T-CPMB May 96* 372-381

packages, pin assignment, ground noise minimization. *Williamson, J.M.*, +, *T-CPMB May 96* 361-371

single chip packages, noise computation. *Bathay, K.*, +, *T-CPMB May 96* 350-360

Integrated circuit packaging

chips-first MCM implement., pass./act. test coupons, HDI. *Schaefner, T.M.*, +, *T-CPMB May 96* 403-416

CMOS chip, simultaneous switching noise. *McCredie, B.D.*, +, *T-CPMB Aug 96* 461-472

CMOS µP, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173

contributions from the 45th Electronic Components and Manufacturing Technology Conference (ECTC) (special section). *T-CPMB May 96* 296-330

contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *Celik, M.*, +, *T-CPMB Aug 96* 692

contributions from the 3rd Topical Meeting on the Electrical Performance of Electronic Packaging (special section). *T-CPMB May 96* 272-295

contributions from the 4th IEEE Topical Meeting on Electrical Performance of Electronic Packaging (special section). *T-CPMB Aug 96* 460-522

convectively cooled substr., transient thermal response. *Fisher, T.S.*, +, *T-CPMB Feb 96* 255-262

COPNA-resin, low temp. curing resin for high-dens. electronic packages. *Nawa, K.*, +, *T-CPMB Aug 96* 585-592

Cu/Sn-Pb solder joints, interfacial fatigue-crack growth, cooling rate effect. *Daping Yao*, +, *T-CPMB Feb 96* 154-165

epoxy 3D MCM, Design and eval. for portable video equipt. *Stern, J.M.*, +, *T-CPMB Feb 96* 188-194

GaAs high-isolation SPDT switch, ultra-compact plastic-packaged develop. *Uda, H.*, +, *T-CPMB Feb 96* 182-187

glass ceramic multichip carriers, press. sintering. *Ho-Ming Tong*, +, *T-CPMB Feb 96* 203-214

ground noise minimization, pin assignment optim. *Williamson, J.M.*, +, *T-CPMB May 96* 361-371

high-dens. electronic package interconnections, design guidelines. *Yang, Y.*, +, *T-CPMB Feb 96* 230-237

inductance matrix meas. *Chi-Taou Tsai*, +, *T-CPMB May 96* 338-343

interconnections, strong coupling lines. *Yaochao Yang*, +, *T-CPMB May 96* 372-381

large pin count electronic packages, capacitance/conductance/resist./inductance matrices. *Young, B.*, +, *T-CPMB Feb 96* 225-229

leadframe packages, simultaneous switching noise design algm. *Huang, C.*, +, *T-CPMB Feb 96* 15-22

leadless MCM-D electronic package, 432-pin land-grid I/O array. *Loos, J.S.*, *T-CPMB Feb 96* 174-181

Level 1 crackfree plastic packaging technol. for VLSI. *Ganesan, G.S.*, +, *T-CPMB Aug 96* 581-584

lossy packaging interconnects, transient simul., moment-matching. *Celik, M.*, +, *T-CPMB Feb 96* 64-73

LSI plastic packages, resin cracking, temp. cyclic loading, stress anal. *Saitoh, T.*, *T-CPMB Aug 96* 593-600

metallized ceramic packages, reliab. assess. *Subbarayan, G.*, +, *T-CPMB Aug 96* 685-691

microwave packaging (special section). *T-CPMB Feb 96* 40-81

MIMIC interconnects, EM field coupling. *Strauss, G.*, +, *T-CPMB May 96* 278-282

mixed-sig. GPS receiver, MCM packaging. *Zabinski, P.J.*, +, *T-CPMB Feb 96* 215-224

MLC package, time-domain meas. and cct. modeling. *Jyh-Ming Jong*, +, *T-CPMB Feb 96* 48-56

optoelectronic MCMs, opt./elec. hybrid packaging techs. *Koike, S.*, +, *T-CPMB Feb 96* 124-130

packaging alternatives to large Si chips, tiled Si on MCM and PWB substrs. *George, A.G.*, +, *T-CPMB Nov 96* 699-708

perform. improvement of memory hierarchy of RISC-systs. by appl. of 3D technol. *Kleiner, M.B.*, +, *T-CPMB Nov 96* 709-718

PQFPs, molding cpd. chem. shrinkage in stress and warpage anal. *Kelly, G.*, +, *T-CPMB May 96* 296-300

semicond. wafers, uniform bump plating, fountain plating cell. *Tien-Yu Tom Lee*, +, *T-CPMB Feb 96* 131-137

single chip packages, noise computation. *Bathay, K.*, +, *T-CPMB May 96* 350-360

tapeless lead-on-chip packages, cracking, adhesive effects. *Amagai, M.*, *T-CPMB May 96* 301-309

very small peripheral array package, charactn. *Jie Hao*, +, *T-CPMB Aug 96* 512-517

Integrated circuit packaging; cf. Multichip modules

Integrated circuit reliability

CMOS µP, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173

Level 1 crackfree plastic packaging technol. for VLSI. *Ganesan, G.S.*, +, *T-CPMB Aug 96* 581-584

low-cost flip-chip on board. *Baggerman, A.F.J.*, +, *T-CPMB Nov 96* 736-746

metallized ceramic packages, reliab. assess. *Subbarayan, G.*, +, *T-CPMB Aug 96* 685-691

solder joint reliab. of flip chip and plastic ball grid array assemblies under thermal, mech., and vibr. conditions. *Lau, J.H.*, *T-CPMB Nov 96* 728-735

Integrated circuits; cf. CMOS integrated circuits; Digital integrated circuits;

High-speed integrated circuits; Integrated optoelectronics; Large-scale integration; Microprocessors; Microwave integrated circuits; UHF integrated circuits

Integrated circuit thermal factors

CMOS µP, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173

convectively cooled substr., transient thermal response. *Fisher, T.S.*, +, *T-CPMB Feb 96* 255-262

Cu/Sn-Pb solder joints, interfacial fatigue-crack growth, cooling rate effect. *Daping Yao*, +, *T-CPMB Feb 96* 154-165

leadless MCM-D electronic package, 432-pin land-grid I/O array. *Loos, J.S.*, *T-CPMB Feb 96* 174-181

Level 1 crackfree plastic packaging technol. for VLSI. *Ganesan, G.S.*, +, *T-CPMB Aug 96* 581-584

LSI plastic packages, resin cracking, temp. cyclic loading, stress anal. *Saitoh, T.*, *T-CPMB Aug 96* 593-600

metallized ceramic packages, reliab. assess. *Subbarayan, G.*, +, *T-CPMB Aug 96* 685-691

porphritic heat sink paste, thermal cond. meas., MCM. *Artus, R.G.C.*, *T-CPMB Aug 96* 601-604

PQFPs, molding cpd. chem. shrinkage in stress and warpage anal. *Kelly, G.*, +, *T-CPMB May 96* 296-300

solder joint reliab. of flip chip and plastic ball grid array assemblies under thermal, mech., and vibr. conditions. *Lau, J.H.*, *T-CPMB Nov 96* 728-735

Integrated optics

2D surface act. devices, optoelectronic packaging. *Basavanhally, N.R.*, +, *T-CPMB Feb 96* 107-115

Integrated optoelectronics

AuSn low temp. bonding of epitaxial lift off devices, optoelectronic ICs. *Dohle, G.R.*, +, *T-CPMB Aug 96* 575-580

contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *T-CPMB Aug 96* 523-580

contributions from the 7th National Meeting of the Lasers and Electro-optics Society (LEOS) (special section). *T-CPMB Feb 96* 82-130

MCM, polyimide waveguide, LD array packaging. *Koike, S.*, +, *T-CPMB Aug 96* 628-634

optoelectronic MCMs, opt./elec. hybrid packaging techs. *Koike, S.*, +, *T-CPMB Feb 96* 124-130
 thin-film multimaterial OEICs, interconnect appls. *Jokerst, N.M.*, +, *T-CPMB Feb 96* 97-106
Integration (math.)
 board connector, high pincount, field-based anal. *Wolter, H.*, +, *T-CPMB Feb 96* 23-31
Interchannel interference; cf. Optical crosstalk
Interconnections; cf. Integrated circuit interconnections; Optical interconnections
Interference; cf. Crosstalk; Electromagnetic interference; Noise
Inverse problems; cf. Deconvolution; Integration (math.)
Iterative methods
 IC interconnect, multilayer dielec., crossover capacitance. *Guang-Wen Pan*, +, *T-CPMB Aug 96* 615-620

J

Junction lasers; cf. Semiconductor lasers
Junctions; cf. Hybrid junctions

L

LAN; cf. Local area networks
Land mobile radio equipment
 RF wireless systs., antenna modeling and design. *Ponnappalli, S.*, *T-CPMB Aug 96* 487-502
Large-scale integration
 COPNA-resin, low temp. curing resin for high-dens. electronic packages. *Nawa, K.*, +, *T-CPMB Aug 96* 585-592
 plastic packages, resin cracking, temp. cyclic loading, stress anal. *Saitoh, T.*, *T-CPMB Aug 96* 593-600
Large-scale integration; cf. Very-large-scale integration
Laser arrays; cf. Semiconductor laser arrays
Laser bonding; cf. Laser welding
Laser diodes; cf. Semiconductor lasers
Laser modes
 surface mount single-mode LD module, pass. alignment. *Kurata, K.*, +, *T-CPMB Aug 96* 524-531
Lasers; cf. Power lasers
Lasers and Electro-optics Society, 7th National Meeting of the
 contributions (special section). *T-CPMB Feb 96* 82-130
Laser thermal factors
 diode laser arrays, cooling, microchannel heat exchanger. *Roy, S.K.*, +, *T-CPMB May 96* 444-451
 VCSEL-based optoelectronic modules, thermal mgt. *Yung-Cheng Lee*, +, *T-CPMB Aug 96* 540-547
Laser welding
 defect form. mechanisms in laser welding techs. for semicond. laser packaging. *Cheng, W.-H.*, +, *T-CPMB Nov 96* 764-769
 laser weldability anal. of high-speed opt. transm. device packaging. *Song, M.K.*, +, *T-CPMB Nov 96* 758-763

Layout
 flat spiral delay line design, min. crosstalk penalty. *Ruey-Beei Wu*, +, *T-CPMB May 96* 397-402
 multiconductor coupled transm. lines, inter-chip interconnects, crosstalk estim. *Gordon, C.*, +, *T-CPMB May 96* 273-277
Layout; cf. Layout of circuit boards; Layout of integrated circuits
Layout of circuit boards
 CMOS μ p, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173
 leadless MCM-D electronic package, 432-pin land-grid I/O array. *Loos, J.S.*, *T-CPMB Feb 96* 174-181
 sig. pin dens. limitations on wiring boards. *Chiba, T.*, +, *T-CPMB May 96* 391-396

Layout of integrated circuits
 GaAs high-isolation SPDT switch, ultra-compact plastic-packaged develop. *Uda, H.*, +, *T-CPMB Feb 96* 182-187
Lead bonding
 AuSn alloy bonding tech., microwave devices. *Rainer Dohle, G.*, +, *T-CPMB Feb 96* 57-63
 TAB-OLB contacts, 75 μ m pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147
 tapeless lead-on-chip packages, cracking, adhesive effects. *Amagai, M.*, *T-CPMB May 96* 301-309
 VCSEL-based optoelectronic modules, thermal mgt. *Yung-Cheng Lee*, +, *T-CPMB Aug 96* 540-547

Lead materials/devices
 Cu/Sn-Pb solder joints, interfacial fatigue-crack growth, cooling rate effect. *Daping Yao*, +, *T-CPMB Feb 96* 154-165
 pore-free reflow soldering. *Xie, D.J.*, +, *T-CPMB Feb 96* 148-153
Lenses
 2D surface act. devices, optoelectronic packaging. *Basavanhally, N.R.*, +, *T-CPMB Feb 96* 107-115

Linear algebra; cf. Matrices**Local area networks**

high speed opt. transceiver, two-step overmold packaging technol., FDDI and FCLANs. *Anigbo, F.C.J.*, +, *T-CPMB Aug 96* 562-568

Logic arrays

leadless MCM-D electronic package, 432-pin land-grid I/O array. *Loos, J.S.*, *T-CPMB Feb 96* 174-181

Logic arrays; cf. Programmable logic arrays**Logic circuits**

appl. of path integrals in modeling transm. line loss. *Rubin, L.M.*, *T-CPMB Nov 96* 775-788

Logic circuits; cf. Logic arrays; Transistor-transistor logic**Losses**

chips-first MCM implement., pass./act. test coupons, HDI. *Schaefer, T.M.*, +, *T-CPMB May 96* 403-416

Losses; cf. Dielectric losses; Skin effect**Lossy circuits**

appl. of path integrals in modeling transm. line loss. *Rubin, L.M.*, *T-CPMB Nov 96* 775-788

contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *Celik, M.*, +, *T-CPMB Aug 96* 692

lossy packaging interconnects, transient simul., moment-matching. *Celik, M.*, +, *T-CPMB Feb 96* 64-73

LSI; cf. Large-scale integration**M****Magnetic resonance; cf. Nuclear magnetic resonance****Magnetostatics**

3D interconnect struct., freq.-depend. coupling inductances, reduced-order modeling. *Miguel Silveira, L.*, +, *T-CPMB May 96* 283-288

Manufacturing economics

struct. test methodologies and test economics for MCM. *Kornegay, K.T.*, +, *T-CPMB Feb 96* 195-202

Manufacturing testing

struct. test methodologies and test economics for MCM. *Kornegay, K.T.*, +, *T-CPMB Feb 96* 195-202

Materials processing

glass ceramic multichip carriers, press. sintering. *Ho-Ming Tong*, +, *T-CPMB Feb 96* 203-214

Materials processing; cf. Bonding**Materials testing**

defect-free solder joints, reflow soldering fab., fatigue life study. *Xie, D.J.*, +, *T-CPMB Aug 96* 679-684

Matrices

extraction of capacitance matrix of multiconductor interconnection lines for high-speed IC syst. design. *Luo, S.-P.*, +, *T-CPMB Nov 96* 770-774

packages, inductance matrix meas. *Chi-Taou Tsai*, +, *T-CPMB May 96* 338-343

Matrices; cf. Moment methods**MCM; cf. Multichip modules**

Measurement; cf. Integrated circuit measurements; Time domain measurements; Spectroscopy

Mechanical factors

anisotropically conductive adhesive flip-chip bonding, expt. study. *Zonghe Lai*, +, *T-CPMB Aug 96* 644-660

ball-grid array packages, design and proc. *Heinrich, S.M.*, +, *T-CPMB May 96* 310-319

defect-free solder joints, reflow soldering fab., fatigue life study. *Xie, D.J.*, +, *T-CPMB Aug 96* 679-684

fully imidized polyimide films, adhesion enhancement and lamination, packaging appls. *Stoffel, N.C.*, +, *T-CPMB May 96* 417-422

metallized ceramic packages, reliab. assess. *Subbarayan, G.*, +, *T-CPMB Aug 96* 685-691

surface mount solder joints, fatigue life estim. *Xie, D.J.*, +, *T-CPMB Aug 96* 669-678

surface mount solder joints reliab. study, effect of Cu-Sn alloys. *So, A.C.K.*, +, *T-CPMB Aug 96* 661-668

Mechanical factors; cf. Contact mechanical factors; Integrated circuit mechanical factors; Strain; Stress

Mechanical systems; cf. Microelectromechanical devices**Mechatronics; cf. Microelectromechanical devices****Memories; cf. Cache memories****Memory hierarchies**

perform. improvement of memory hierarchy of RISC-systs. by appl. of 3D technol. *Kleiner, M.B.*, +, *T-CPMB Nov 96* 709-718

MESFET integrated circuits

GaAs high-isolation SPDT switch, ultra-compact plastic-packaged develop. *Uda, H.*, +, *T-CPMB Feb 96* 182-187

MESFET switches

GaAs high-isolation SPDT switch, ultra-compact plastic-packaged develop. *Uda, H.*, +, *T-CPMB Feb 96* 182-187

Metallization

TAB-OLB contacts, 75 μ m pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147

- Metal materials/devices; cf.** Aluminum materials/devices; Gallium materials/devices; Indium materials/devices; Lead materials/devices; Tin materials/devices
- Meteorology; cf.** Humidity
- MIC; cf.** Microwave integrated circuits
- Microcomputers; cf.** Microprocessors
- Microelectromechanical devices**
- opt. fiber array alignment, micromachined device, photonic packaging. *Kravitz, S.H.*, +, *T-CPMB Feb 96* 83-89
 - thin-film multimaterial OEICs, interconnect appls. *Jokerst, N.M.*, +, *T-CPMB Feb 96* 97-106
- Microprocessors**
- CMOS μP, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173
 - perform. modeling of interconnect struct. of 3D integrated RISC processor/cache syst. *Kuhn, S.A.*, +, *T-CPMB Nov 96* 719-727
- Microscopy**
- AuSn low temp. bonding of epitaxial lift off devices, optoelectronic ICs. *Dohle, G.R.*, +, *T-CPMB Aug 96* 575-580
- Microscope; cf.** Electron microscopy
- Microstrip**
- chips-first MCM implement., pass./act. test coupons, HDI. *Schaefer, T.M.*, +, *T-CPMB May 96* 403-416
- Microstrip discontinuities**
- microelectronic interconnects, transm. line params. meas. *Abernethy, C.E.*, +, *T-CPMB Feb 96* 32-39
- Microwave circuits; cf.** Microwave integrated circuits; Microwave receivers
- Microwave devices**
- AuSn alloy bonding tech., microwave devices. *Rainer Dohle, G.*, +, *T-CPMB Feb 96* 57-63
- Microwave devices; cf.** Microwave integrated circuits
- Microwave integrated circuits**
- microwave packaging (special section). *T-CPMB Feb 96* 40-81
- Microwave measurements**
- microelectronic interconnects, transm. line params. meas. *Abernethy, C.E.*, +, *T-CPMB Feb 96* 32-39
 - MLC capacitor, HF meas. *Sakabe, Y.*, +, *T-CPMB Feb 96* 7-14
- Microwave receivers**
- mixed-sig. GPS receiver, MCM packaging. *Zabinski, P.J.*, +, *T-CPMB Feb 96* 215-224
- Millimeter wave monolithic integrated circuits; cf.** MIMICs
- MIMICs**
- interconnects, EM field coupling. *Strauss, G.*, +, *T-CPMB May 96* 278-282
- Minimization methods**
- IC packages, pin assignment, ground noise minimization. *Williamson, J.M.*, +, *T-CPMB May 96* 361-371
- Mirrors**
- optoelectronic MCMs, opt./elec. hybrid packaging techs. *Koike, S.*, +, *T-CPMB Feb 96* 124-130
- Mixed analog-digital integrated circuits**
- global positioning syst. receiver, MCM packaging. *Zabinski, P.J.*, +, *T-CPMB Feb 96* 215-224
- Mobile antennas**
- RF wireless systs., antenna modeling and design. *Ponnappalli, S.*, *T-CPMB Aug 96* 487-502
- Modeling**
- contributions from 45th Electronic Components and Technology Conference (ECTC), (special section). *T-CPMB Feb 96* 1-39
- Modeling; cf.** Circuit modeling; Reliability modeling; Semiconductor process modeling
- Model reduction; cf.** Reduced order systems
- Modulation/demodulation; cf.** Heterodyne detection
- Moisture**
- anisotropically conductive adhesive flip-chip bonding, expt. study. *Zonghe Lai*, +, *T-CPMB Aug 96* 644-660
- Moisture; cf.** Humidity
- Moment methods**
- correction to "Efficient transient simulation of lossy packaging interconnects using moment-matching techniques" (Feb 96 64-73). *Celik, M.*, +, *T-CPMB Aug 96* 692
 - lossy packaging interconnects, transient simul., moment-matching. *Celik, M.*, +, *T-CPMB Feb 96* 64-73
 - RF wireless systs., antenna modeling and design. *Ponnappalli, S.*, *T-CPMB Aug 96* 487-502
- Monolithic integrated circuits; cf.** MIMICs
- MOS integrated circuits; cf.** CMOS integrated circuits
- Multipchip modules**
- approaching uniform bump height of electroplated solder bumps on silicon wafer. *Lin, K.-L.*, +, *T-CPMB Nov 96* 747-751
 - chips-first MCM implement., pass./act. test coupons, HDI. *Schaefer, T.M.*, +, *T-CPMB May 96* 403-416
 - correction to "A silicon-on-silicon field programmable multipchip module (FPMCM) - Integrating FPGA and MCM technologies" (Nov 95 601-608). *Darnauer, J.*, +, *T-CPMB Feb 96* 263
 - epoxy 3D MCM, Design and eval. for portable video equip. *Stern, J.M.*, +, *T-CPMB Feb 96* 188-194

- HF interconnects, BCB adhesive. *Krishnamurthy, V.B.*, +, *T-CPMB Feb 96* 42-47
- high Q-factor inductors integrated on MCM Si substrs. *Zu, L.*, +, *T-CPMB Aug 96* 635-643
- interconnections, freq. and time domain anal. *Salik, R.*, +, *T-CPMB Feb 96* 74-81
- leadless MCM-D electronic package, 432-pin land-grid I/O array. *Loos, J.S.*, *T-CPMB Feb 96* 174-181
- metallized ceramic packages, reliab. assess. *Subbarayan, G.*, +, *T-CPMB Aug 96* 685-691
- microwave packaging (special section). *T-CPMB Feb 96* 40-81
- mixed-sig. GPS receiver, MCM packaging. *Zabinski, P.J.*, +, *T-CPMB Feb 96* 215-224
- opto-electronic MCM, polyimide waveguide, LD array packaging. *Koike, S.*, +, *T-CPMB Aug 96* 628-634
- optoelectronic MCMs, opt./elec. hybrid packaging techs. *Koike, S.*, +, *T-CPMB Feb 96* 124-130
- packaging alternatives to large Si chips, tiled Si on MCM and PWB substrs. *George, A.G.*, +, *T-CPMB Nov 96* 699-708
- parallel digital opt. receiver array module, hybrid packaging, 622 Mb/s/channel. *Siala, S.*, +, *T-CPMB Aug 96* 548-553
- polyimide-Cu thin-film multilayer interconnects on ceramic substr. *Bedouani, M.*, +, *T-CPMB May 96* 382-390
- porphritic heat sink paste, thermal cond. meas., MCM. *Artus, R.G.C.*, *T-CPMB Aug 96* 601-604
- self-aligned MCM-D based opt. data links, opt. perform. *Dautartas, M.F.*, +, *T-CPMB Aug 96* 554-561
- struct. test methodologies and test economics for MCM. *Kornegay, K.T.*, +, *T-CPMB Feb 96* 195-202

Multiconductor transmission lines

- extraction of capacitance matrix of multiconductor interconnection lines for high-speed IC syst. design. *Luo, S.-P.*, +, *T-CPMB Nov 96* 770-774
- multiconductor coupled transm. lines, inter-chip interconnects, crosstalk estim. *Gordon, C.*, +, *T-CPMB May 96* 273-277

Multimode transmission lines; cf.

Multimode waveguides

- Multimode waveguides**
- parallel digital opt. receiver array module, hybrid packaging, 622 Mb/s/channel. *Siala, S.*, +, *T-CPMB Aug 96* 548-553
 - self-aligned MCM-D based opt. data links, opt. perform. *Dautartas, M.F.*, +, *T-CPMB Aug 96* 554-561

Multiport circuits

- MLC package, time-domain meas. and cct. modeling. *Jyh-Ming Jong*, +, *T-CPMB Feb 96* 48-56

Multiport circuits; cf.

Two-port circuits

Mutual coupling; cf.

Coupled transmission lines

N

NMR; cf.

Nuclear magnetic resonance

Noise

- contributions from the 4th IEEE Topical Meeting on Electrical Performance of Electronic Packaging (special section). *T-CPMB Aug 96* 460-522

Noise; cf.

Circuit noise; Electromagnetic interference

Nonhomogeneous media

- fully imidized polyimide films, adhesion enhancement and lamination, packaging appls. *Stoffel, N.C.*, +, *T-CPMB May 96* 417-422

Nonuniformly spaced arrays

- ball-grid array packages, design and proc. *Heinrich, S.M.*, +, *T-CPMB May 96* 310-319

Nonuniform transmission lines; cf.

Distributed parameter circuits

N-port circuits; cf.

Multiport circuits

Nuclear magnetic resonance

- COPNA-resin, low temp. curing resin for high-dens. electronic packages. *Nawa, K.*, +, *T-CPMB Aug 96* 585-592

Numerical analysis; cf.

Finite difference methods; Finite element methods; Iterative methods; Moment methods

O

Optical arrays

- 2D surface act. devices, optoelectronic packaging. *Basavanhally, N.R.*, +, *T-CPMB Feb 96* 107-115

- opt. fiber array alignment, micromachined device, photonic packaging. *Kravitz, S.H.*, +, *T-CPMB Feb 96* 83-89

- single-mode opt. fiber interconnects, Si waferboard. *Haugsjaa, P.O.*, +, *T-CPMB Feb 96* 90-96

Optical communication; cf.

Optical fiber communication

Optical communication equipment

- high speed opt. transceiver, two-step overmold packaging technol., FDDI and FCLANs. *Anigbo, F.C.J.*, +, *T-CPMB Aug 96* 562-568

- opto-electronic MCM, polyimide waveguide, LD array packaging. *Koike, S.*, +, *T-CPMB Aug 96* 628-634

- surface mount single-mode LD module, pass. alignment. *Kurata, K.*, +, *T-CPMB Aug 96* 524-531

- Optical communication equipment; cf.** Optical receivers; Optical transmitters
- Optical components; cf.** Lenses; Mirrors
- Optical couplers**
- optoelectronic MCMs, opt./elec. hybrid packaging techs. *Koike, S., +, T-CPMB Feb 96* 124-130
- Optical couplers; cf.** Optical fiber couplers
- Optical coupling**
- surface mount single-mode LD module, pass. alignment. *Kurata, K., +, T-CPMB Aug 96* 524-531
- Optical coupling; cf.** Optical fiber coupling
- Optical crosstalk**
- high speed opt. transceiver, two-step overmold packaging technol., FDDI and FCLANs. *Anigbo, F.C.J., +, T-CPMB Aug 96* 562-568
- Optical detectors; cf.** Photodetectors
- Optical distortion; cf.** Optical crosstalk
- Optical fiber applications**
- contributions from the 7th National Meeting of the Lasers and Electro-optics Society (LEOS) (special section). *T-CPMB Feb 96* 82-130
- Optical fiber communication**
- high speed opt. transceiver, two-step overmold packaging technol., FDDI and FCLANs. *Anigbo, F.C.J., +, T-CPMB Aug 96* 562-568
 - multichannel opt. modules compatible, fiber-in-board technol. *De pestel, G., +, T-CPMB Feb 96* 116-123
 - Optobus low-cost high-perform. opt. interconnect. *Schwartz, D.B., +, T-CPMB Aug 96* 532-539
 - parallel digital opt. receiver array module, hybrid packaging, 622 Mb/s/channel. *Siala, S., +, T-CPMB Aug 96* 548-553
 - single-mode opt. fiber interconnects, Si waferboard. *Haugsjaa, P.O., +, T-CPMB Feb 96* 90-96
 - surface mount single-mode LD module, pass. alignment. *Kurata, K., +, T-CPMB Aug 96* 524-531
- Optical fiber communication; cf.** FDDI
- Optical fiber connecting**
- high speed opt. transceiver, two-step overmold packaging technol., FDDI and FCLANs. *Anigbo, F.C.J., +, T-CPMB Aug 96* 562-568
 - single-mode opt. fiber interconnects, Si waferboard. *Haugsjaa, P.O., +, T-CPMB Feb 96* 90-96
- Optical fiber couplers**
- 90°-hybrid bal. opt. receiver using planar lightwave cct., packaging tech. *Tsunetsugu, H., +, T-CPMB Aug 96* 569-574
- Optical fiber coupling**
- optoelectronic MCMs, opt./elec. hybrid packaging techs. *Koike, S., +, T-CPMB Feb 96* 124-130
 - self-aligned MCM-D based opt. data links, opt. perform. *Dautartas, M.F., +, T-CPMB Aug 96* 554-561
- Optical fibers**
- array alignment, micromachined device, photonic packaging. *Kravitz, S.H., +, T-CPMB Feb 96* 83-89
- Optical fiber thermal factors**
- high speed opt. transceiver, two-step overmold packaging technol., FDDI and FCLANs. *Anigbo, F.C.J., +, T-CPMB Aug 96* 562-568
- Optical films; cf.** Optical planar waveguides
- Optical image processing**
- thin-film multimaterial OEICs, interconnect appls. *Jokerst, N.M., +, T-CPMB Feb 96* 97-106
- Optical interconnections**
- 90°-hybrid bal. opt. receiver using planar lightwave cct., packaging tech. *Tsunetsugu, H., +, T-CPMB Aug 96* 569-574
 - contributions from the 7th National Meeting of the Lasers and Electro-optics Society (LEOS) (special section). *T-CPMB Feb 96* 82-130
 - high speed opt. transceiver, two-step overmold packaging technol., FDDI and FCLANs. *Anigbo, F.C.J., +, T-CPMB Aug 96* 562-568
 - multichannel opt. modules compatible, fiber-in-board technol. *De pestel, G., +, T-CPMB Feb 96* 116-123
 - Optobus low-cost high-perform. opt. interconnect. *Schwartz, D.B., +, T-CPMB Aug 96* 532-539
 - optoelectronic MCMs, opt./elec. hybrid packaging techs. *Koike, S., +, T-CPMB Feb 96* 124-130
 - single-mode opt. fiber interconnects, Si waferboard. *Haugsjaa, P.O., +, T-CPMB Feb 96* 90-96
 - thin-film multimaterial OEICs, interconnect appls. *Jokerst, N.M., +, T-CPMB Feb 96* 97-106
- Optical links; cf.** Optical interconnections
- Optical materials/devices**
- opto-electronic MCM, polyimide waveguide, LD array packaging. *Koike, S., +, T-CPMB Aug 96* 628-634
- Optical materials/devices; cf.** Electrooptic materials/devices; Optical rays; Optical couplers; Optical receivers; Optical transmitters; Optical waveguides
- Optical planar waveguides**
- 90°-hybrid bal. opt. receiver using planar lightwave cct., packaging tech. *Tsunetsugu, H., +, T-CPMB Aug 96* 569-574
- Optical propagation; cf.** Optical fibers; Optical planar waveguides; Optical waveguides
- Optical receivers**
- 90°-hybrid bal. opt. receiver using planar lightwave cct., packaging tech. *Tsunetsugu, H., +, T-CPMB Aug 96* 569-574
 - parallel digital opt. receiver array module, hybrid packaging, 622 Mb/s/channel. *Siala, S., +, T-CPMB Aug 96* 548-553
 - single-mode opt. fiber interconnects, Si waferboard. *Haugsjaa, P.O., +, T-CPMB Feb 96* 90-96
 - thin-film multimaterial OEICs, interconnect appls. *Jokerst, N.M., +, T-CPMB Feb 96* 97-106
- Optical reflection; cf.** Mirrors
- Optical signal processing; cf.** Optical image processing
- Optical transmitters**
- single-mode opt. fiber interconnects, Si waferboard. *Haugsjaa, P.O., +, T-CPMB Feb 96* 90-96
- Optical waveguides**
- opto-electronic MCM, polyimide waveguide, LD array packaging. *Koike, S., +, T-CPMB Aug 96* 628-634
 - optoelectronic MCMs, opt./elec. hybrid packaging techs. *Koike, S., +, T-CPMB Feb 96* 124-130
- Optical waveguides; cf.** Optical fibers; Optical planar waveguides
- Optics; cf.** Integrated optics; Ultrafast optics
- Optimization methods; cf.** Circuit optimization; Minimization methods; Simulated annealing
- Optoelectronic devices**
- contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *T-CPMB Aug 96* 523-580
 - contributions from the 7th National Meeting of the Lasers and Electro-optics Society (LEOS) (special section). *T-CPMB Feb 96* 82-130
- Optoelectronic devices; cf.** Integrated optoelectronics; Photodetectors
- Organic materials/devices; cf.** Plastic materials/devices

P**Packaging**

- 3D interconnect struct., freq.-depend. coupling inductances, reduced-order modeling. *Miguel Silveira, L., +, T-CPMB May 96* 283-288
- 90°-hybrid bal. opt. receiver using planar lightwave cct., packaging tech. *Tsunetsugu, H., +, T-CPMB Aug 96* 569-574
- ball-grid array packages, design and proc. *Heinrich, S.M., +, T-CPMB May 96* 310-319
- ball grid array packages, PCB finish, reliab. and wettability. *Bradley, E., +, T-CPMB May 96* 320-330
- contributions from 45th Electronic Components and Technology Conference (ECTC), (special section). *T-CPMB Feb 96* 1-39
- contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *T-CPMB Aug 96* 523-580
- contributions from the 4th IEEE Topical Meeting on Electrical Performance of Electronic Packaging (special section). *T-CPMB Aug 96* 460-522
- flat spiral delay line design, min. crosstalk penalty. *Ruey-Beei Wu, +, T-CPMB May 96* 397-402
- fully imidized polyimide films, adhesion enhancement and lamination, packaging appls. *Stoffel, N.C., +, T-CPMB May 96* 417-422
- high speed opt. transceiver, two-step overmold packaging technol., FDDI and FCLANs. *Anigbo, F.C.J., +, T-CPMB Aug 96* 562-568
- integral decoupling capacitors, time/freq. domain anal. *Goetz, M.P., T-CPMB Aug 96* 518-522
- laser weldability anal. of high-speed opt. transm. device packaging. *Song, M.K., +, T-CPMB Nov 96* 758-763
- microwave packaging (special section). *T-CPMB Feb 96* 40-81
- multichannel opt. modules compatible, fiber-in-board technol. *De pestel, G., +, T-CPMB Feb 96* 116-123
- multiconductor coupled transm. lines, inter-chip interconnects, crosstalk estim. *Gordon, C., +, T-CPMB May 96* 273-277
- opt. fiber array alignment, micromachined device, photonic packaging. *Kravitz, S.H., +, T-CPMB Feb 96* 83-89
- Optobus low-cost high-perform. opt. interconnect. *Schwartz, D.B., +, T-CPMB Aug 96* 532-539
- parallel digital opt. receiver array module, hybrid packaging, 622 Mb/s/channel. *Siala, S., +, T-CPMB Aug 96* 548-553
- sig. pin dens. limitations on wiring boards. *Chiba, T., +, T-CPMB May 96* 391-396
- temp. and stress time hist. responses in electronic packaging. *Lau, J.H., T-CPMB Feb 96* 248-254
- two-port interconnection struct., cct. modeling, causality. *Sercu, S., +, T-CPMB May 96* 289-295
- VCSEL-based optoelectronic modules, thermal mgt. *Yung-Cheng Lee, +, T-CPMB Aug 96* 540-547

- Packaging; cf.** Encapsulation; Integrated circuit packaging; Plastic packaging; Semiconductor device packaging

Parallel architectures

- multichannel opt. modules compatible, fiber-in-board technol. *De pestel, G., +, T-CPMB Feb 96* 116-123

- thin-film multimaterial OEICs, interconnect appls. *Jokerst, N.M.*, +, *T-CPMB Feb 96* 97-106
- Permittivity**
COPNA-resin, low temp. curing resin for high-dens. electronic packages. *Nawa, K.*, +, *T-CPMB Aug 96* 585-592
cyanate ester PCB material, dielec. const. and loss. *Deutsch, A.*, +, *T-CPMB May 96* 331-337
- Phase distortion; cf. Delay effects**
- Phase shift keying**
90°-hybrid bal. opt. receiver using planar lightwave cct., packaging tech. *Tsunetsugu, H.*, +, *T-CPMB Aug 96* 569-574
- Photodetectors**
thin-film multimaterial OEICs, interconnect appls. *Jokerst, N.M.*, +, *T-CPMB Feb 96* 97-106
- Photodiodes; cf. p-i-n photodiodes**
- Photonics; cf. Optical materials/devices**
- p-i-n photodiodes**
90°-hybrid bal. opt. receiver using planar lightwave cct., packaging tech. *Tsunetsugu, H.*, +, *T-CPMB Aug 96* 569-574
- PLA; cf. Programmable logic arrays**
- Planar transmission lines**
polyimide-Cu thin-film multilayer interconnects on ceramic substr. *Bedouani, M.*, +, *T-CPMB May 96* 382-390
- Planar transmission lines; cf. Microstrip; Optical planar waveguides; Stripline**
- Planar waveguides; cf. Optical planar waveguides; Planar transmission lines**
- Plastic films**
anisotropic conductive film with arrayed conductive particles. *Ishibashi, K.*, +, *T-CPMB Nov 96* 752-757
- Plastic films; cf. Polyimide films**
- Plastic materials/devices**
cyanate ester PCB material, dielec. const. and loss. *Deutsch, A.*, +, *T-CPMB May 96* 331-337
MCM, HF interconnects, BCB adhesive. *Krishnamurthy, V.B.*, +, *T-CPMB Feb 96* 42-47
opto-electronic MCM, polyimide waveguide, LD array packaging. *Koike, S.*, +, *T-CPMB Aug 96* 628-634
optoelectronic MCMS, opt./elec. hybrid packaging techs. *Koike, S.*, +, *T-CPMB Feb 96* 124-130
- Plastic materials/devices; cf. Epoxy resin materials/devices; Plastic films; Plastic packaging**
- Plastic packaging**
EPBGA packages, cavity-up, thermal perform. *Mertol, A.*, *T-CPMB May 96* 427-443
GaAs high-isolation SPDT switch, ultra-compact plastic-packaged develop. *Uda, H.*, +, *T-CPMB Feb 96* 182-187
leadframe packages, simultaneous switching noise design algm. *Huang, C.*, +, *T-CPMB Feb 96* 15-22
Level 1 crackfree plastic packaging technol. for VLSI. *Ganesan, G.S.*, +, *T-CPMB Aug 96* 581-584
LSI plastic packages, resin cracking, temp. cyclic loading, stress anal. *Saitoh, T.*, *T-CPMB Aug 96* 593-600
PQFPs, molding cpd. chem. shrinkage in stress and warpage anal. *Kelly, G.*, +, *T-CPMB May 96* 296-300
- Polyimide films**
fully imidized polyimide films, adhesion enhancement and lamination, packaging appls. *Stoffel, N.C.*, +, *T-CPMB May 96* 417-422
opto-electronic MCM, polyimide waveguide, LD array packaging. *Koike, S.*, +, *T-CPMB Aug 96* 628-634
optoelectronic MCMS, opt./elec. hybrid packaging techs. *Koike, S.*, +, *T-CPMB Feb 96* 124-130
polyimide-Cu thin-film multilayer interconnects on ceramic substr. *Bedouani, M.*, +, *T-CPMB May 96* 382-390
- Polymers; cf. Plastic materials/devices**
- Power lasers**
diode laser arrays, cooling, microchannel heat exchanger. *Roy, S.K.*, +, *T-CPMB May 96* 444-451
- Printed circuit fabrication**
anisotropically conductive adhesive flip-chip bonding, expt. study. *Zonghe Lai*, +, *T-CPMB Aug 96* 644-660
ball grid array packages, PCB finish, reliab. and wettability. *Bradley, E.*, +, *T-CPMB May 96* 320-330
CMOS μP, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173
cyanate ester PCB material, dielec. const. and loss. *Deutsch, A.*, +, *T-CPMB May 96* 331-337
pore-free reflow soldering. *Xie, D.J.*, +, *T-CPMB Feb 96* 148-153
- Printed circuit fabrication; cf. Surface mounting**
- Printed circuits**
connector, high pincount, field-based anal. *Wolter, H.*, +, *T-CPMB Feb 96* 23-31
connectors, high-pincount, SPICE-models. *Katzier, H.*, +, *T-CPMB Feb 96* 3-6
defect-free solder joints, reflow soldering fab., fatigue life study. *Xie, D.J.*, +, *T-CPMB Aug 96* 679-684
multichannel opt. modules compatible, fiber-in-board technol. *De pestel, G.*, +, *T-CPMB Feb 96* 116-123
- packaging alternatives to large Si chips, tiled Si on MCM and PWB substrs. *George, A.G.*, +, *T-CPMB Nov 96* 699-708
surface mount solder joints, fatigue life estim. *Xie, D.J.*, +, *T-CPMB Aug 96* 669-678
TAB-OLB contacts, 75 μm pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147
- Printed circuits; cf. Layout of circuit boards**
- Printing**
thick film ccts., screen printing resoln. rel., surface energies. *Liang, T.-X.*, +, *T-CPMB May 96* 423-426
- Programmable circuits; cf. Programmable logic arrays**
- Programmable logic arrays**
correction to "A silicon-on-silicon field programmable multichip module (FPMCM) - Integrating FPGA and MCM technologies" (Nov 95 601-608). *Darnauer, J.*, +, *T-CPMB Feb 96* 263
- PSK; cf. Phase shift keying**
- Q**
- Quantum well devices; cf. Self-electrooptic-effect devices**
- R**
- Radiation detectors; cf. Photodetectors**
- Radio communication equipment; cf. Land mobile radio equipment**
- Radiography**
pore-free reflow soldering. *Xie, D.J.*, +, *T-CPMB Feb 96* 148-153
- Radio receivers; cf. Microwave receivers**
- Random access memories; cf. SRAM chips**
- Receivers; cf. Microwave receivers; Optical receivers**
- Reduced order systems**
3D interconnect struct., freq.-depend. coupling inductances, reduced-order modeling. *Miguel Silveira, L.*, +, *T-CPMB May 96* 283-288
- Reflection; cf. Mirrors**
- Refrigeration; cf. Cooling**
- Relaxation methods; cf. Simulated annealing**
- Reliability**
ball grid array packages, PCB finish, reliab. and wettability. *Bradley, E.*, +, *T-CPMB May 96* 320-330
surface mount solder joints reliab. study, effect of Cu-Sn alloys. *So, A.C.K.*, +, *T-CPMB Aug 96* 661-668
- Reliability; cf. Circuit reliability; Failure analysis**
- Reliability modeling**
ball-grid array packages, design and proc. *Heinrich, S.M.*, +, *T-CPMB May 96* 310-319
- Reliability testing**
anisotropically conductive adhesive flip-chip bonding, expt. study. *Zonghe Lai*, +, *T-CPMB Aug 96* 644-660
metallized ceramic packages, reliab. assess. *Subbarayan, G.*, +, *T-CPMB Aug 96* 685-691
TAB-OLB contacts, 75 μm pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147
- Resin materials/devices**
COPNA-resin, low temp. curing resin for high-dens. electronic packages. *Nawa, K.*, +, *T-CPMB Aug 96* 585-592
LSI plastic packages, resin cracking, temp. cyclic loading, stress anal. *Saitoh, T.*, *T-CPMB Aug 96* 593-600
- Resin materials/devices; cf. Epoxy resin materials/devices**
- Resistance; cf. Skin effect**
- Resistance measurement**
large pin count electronic packages, capacitance/conductance/resist./inductance matrices. *Young, B.*, +, *T-CPMB Feb 96* 225-229
- S**
- Satellite navigation systems; cf. Global Positioning System**
- Scattering parameters**
board connector, high pincount, field-based anal. *Wolter, H.*, +, *T-CPMB Feb 96* 23-31
contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *Celik, M.*, +, *T-CPMB Aug 96* 692
high Q-factor inductors integrated on MCM Si substrs. *Zu, L.*, +, *T-CPMB Aug 96* 635-643
lossy packaging interconnects, transient simul., moment-matching. *Celik, M.*, +, *T-CPMB Feb 96* 64-73
- Seals**
glass ceramic multichip carriers, press. sintering. *Ho-Ming Tong*, +, *T-CPMB Feb 96* 203-214
- MIMIC interconnects, EM field coupling. *Strauss, G.*, +, *T-CPMB May 96* 278-282**

Self-electrooptic-effect devices

2D surface act. devices, optoelectronic packaging. *Basavanhally, N.R.*, +, *T-CPMB Feb 96* 107-115

Semiconductor device bonding

2D surface act. devices, optoelectronic packaging. *Basavanhally, N.R.*, +, *T-CPMB Feb 96* 107-115

approaching uniform bump height of electroplated solder bumps on silicon wafer. *Lin, K.-L.*, +, *T-CPMB Nov 96* 747-751

AuSn alloy bonding tech., microwave devices. *Rainer Dohle, G.*, +, *T-CPMB Feb 96* 57-63

defect form. mechanisms in laser welding techs. for semicond. laser packaging. *Cheng, W.-H.*, +, *T-CPMB Nov 96* 764-769

Semiconductor device bonding; cf. Integrated circuit bonding**Semiconductor device fabrication; cf. Integrated circuit fabrication; Semiconductor device bonding, Semiconductor device packaging****Semiconductor device mechanical factors; cf. Integrated circuit mechanical factors; Microelectromechanical devices****Semiconductor device packaging**

2D surface act. devices, optoelectronic packaging. *Basavanhally, N.R.*, +, *T-CPMB Feb 96* 107-115

defect form. mechanisms in laser welding techs. for semicond. laser packaging. *Cheng, W.-H.*, +, *T-CPMB Nov 96* 764-769

surface mount single-mode LD module, pass. alignment. *Kurata, K.*, +, *T-CPMB Aug 96* 524-531

Semiconductor device packaging; cf. Integrated circuit packaging**Semiconductor devices; cf. Integrated circuits; Semiconductor lasers****Semiconductor device thermal factors**

2D surface act. devices, optoelectronic packaging. *Basavanhally, N.R.*, +, *T-CPMB Feb 96* 107-115

Semiconductor device thermal factors; cf. Integrated circuit thermal factors**Semiconductor laser arrays**

diode laser arrays, cooling, microchannel heat exchanger. *Roy, S.K.*, +, *T-CPMB May 96* 444-451

opto-electronic MCM, polyimide waveguide, LD array packaging. *Koike, S.*, +, *T-CPMB Aug 96* 628-634

Semiconductor lasers

defect form. mechanisms in laser welding techs. for semicond. laser packaging. *Cheng, W.-H.*, +, *T-CPMB Nov 96* 764-769

laser weldability anal. of high-speed opt. transm. device packaging. *Song, M.K.*, +, *T-CPMB Nov 96* 758-763

surface mount single-mode LD module, pass. alignment. *Kurata, K.*, +, *T-CPMB Aug 96* 524-531

Semiconductor lasers; cf. Surface-emitting lasers**Semiconductor process modeling**

wafers, uniform bump plating, fountain plating cell. *Tien-Yu Tom Lee*, +, *T-CPMB Feb 96* 131-137

Shielding; cf. Electromagnetic shielding**Silicon materials/devices**

high Q-factor inductors integrated on MCM Si substrs. *Zu, L.*, +, *T-CPMB Aug 96* 635-643

single-mode opt. fiber interconnects, Si waferboard. *Haugsjaa, P.O.*, +, *T-CPMB Feb 96* 90-96

Simulated annealing

IC packages, pin assignment, ground noise minimization. *Williamson, J.M.*, +, *T-CPMB May 96* 361-371

Simulation; cf. Circuit simulation**Skin effect**

high Q-factor inductors integrated on MCM Si substrs. *Zu, L.*, +, *T-CPMB Aug 96* 635-643

Soldering

2D surface act. devices, optoelectronic packaging. *Basavanhally, N.R.*, +, *T-CPMB Feb 96* 107-115

approaching uniform bump height of electroplated solder bumps on silicon wafer. *Lin, K.-L.*, +, *T-CPMB Nov 96* 747-751

ball-grid array packages, design and proc. *Heinrich, S.M.*, +, *T-CPMB May 96* 310-319

ball grid array packages, PCB finish, reliab. and wettability. *Bradley, E.*, +, *T-CPMB May 96* 320-330

CMOS μ P, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173

Cu/Sn-Pb solder joints, interfacial fatigue-crack growth, cooling rate effect. *Daping Yao*, +, *T-CPMB Feb 96* 154-165

defect-free solder joints, reflow soldering fab., fatigue life study. *Xie, D.J.*, +, *T-CPMB Aug 96* 679-684

low-cost flip-chip on board. *Baggerman, A.F.J.*, +, *T-CPMB Nov 96* 736-746

optoelectronic MCMs, opt./elec. hybrid packaging techs. *Koike, S.*, +, *T-CPMB Feb 96* 124-130

pore-free reflow soldering. *Xie, D.J.*, +, *T-CPMB Feb 96* 148-153

solder joint reliab. of flip chip and plastic ball grid array assemblies under thermal, mech., and vibr. conditions. *Lau, J.H.*, *T-CPMB Nov 96* 728-735

surface mount solder joints, fatigue life estim. *Xie, D.J.*, +, *T-CPMB Aug 96* 669-678

surface mount solder joints reliab. study, effect of Cu-Sn alloys. *So, A.C.K.*, +, *T-CPMB Aug 96* 661-668

TAB-OLB contacts, 75 μ m pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147

Solid lasers; cf. Semiconductor lasers**Special issues/sections**

contributions from 45th Electronic Components and Technology Conference (ECTC), (special section). *T-CPMB Feb 96* 1-39

contributions from the 45th Electronic Components and Manufacturing Technology Conference (ECTC) (special section). *T-CPMB May 96* 296-330

contributions from the 45th Electronic Components and Technology Conference, optoelectronic packaging (special section). *T-CPMB Aug 96* 523-580

contributions from the 3rd Topical Meeting on the Electrical Performance of Electronic Packaging (special section). *T-CPMB May 96* 272-295

contributions from the 4th IEEE Topical Meeting on Electrical Performance of Electronic Packaging (special section). *T-CPMB Aug 96* 460-522

contributions from the 7th National Meeting of the Lasers and Electro-optics Society (LEOS) (special section). *T-CPMB Feb 96* 82-130

microwave packaging (special section). *T-CPMB Feb 96* 40-81

Spectroscopy; cf. Infrared spectroscopy; UHF spectroscopy**SPICE**

BiCMOS off-chip driver, simultaneous switching noise. *Secker, D.A.*, +, *T-CPMB Aug 96* 473-480

board connectors, high-pincount, SPICE-models. *Katzier, H.*, +, *T-CPMB Feb 96* 3-6

CMOS ccts., simultaneous switching noise, vel. saturation. *Vemuru, S.R.*, *T-CPMB May 96* 344-349

CMOS off-chip driver, design, simultaneous switching noise. *Yaochao Yang*, +, *T-CPMB Aug 96* 481-486

flat spiral delay line design, min. crosstalk penalty. *Ruey-Beei Wu*, +, *T-CPMB May 96* 397-402

leadframe packages, simultaneous switching noise design algm. *Huang, C.*, +, *T-CPMB Feb 96* 15-22

package interconnections, strong coupling lines. *Yaochao Yang*, +, *T-CPMB May 96* 372-381

Sputter etching

COPNA-resin, low temp. curing resin for high-dens. electronic packages. *Nawa, K.*, +, *T-CPMB Aug 96* 585-592

Sputtering; cf. Sputter etching**SRAM chips**

CMOS SRAM chip, interconnect propag. delay model. *Rayapati, V.N.*, +, *T-CPMB Aug 96* 605-614

Strain

ball-grid array packages, design and proc. *Heinrich, S.M.*, +, *T-CPMB May 96* 310-319

electronic packaging, temp. and stress time hist. responses. *Lau, J.H.*, *T-CPMB Feb 96* 248-254

Stress

anisotropically conductive adhesive flip-chip bonding, expt. study. *Zonghe Lai*, +, *T-CPMB Aug 96* 644-660

electronic packaging, temp. and stress time hist. responses. *Lau, J.H.*, *T-CPMB Feb 96* 248-254

LSI plastic packages, resin cracking, temp. cyclic loading, stress anal. *Saitoh, T.*, *T-CPMB Aug 96* 593-600

surface mount solder joints, fatigue life estim. *Xie, D.J.*, +, *T-CPMB Aug 96* 669-678

Stripline

chips-first MCM implement., pass./act. test coupons, HDI. *Schaefer, T.M.*, +, *T-CPMB May 96* 403-416

multiconductor coupled transm. lines, inter-chip interconnects, crosstalk estim. *Gordon, C.*, +, *T-CPMB May 96* 273-277

Strip transmission lines; cf. Planar transmission lines**Surface-emitting lasers**

2D surface act. devices, optoelectronic packaging. *Basavanhally, N.R.*, +, *T-CPMB Feb 96* 107-115

Optobus, low-cost high-perform. opt. interconnect. *Schwartz, D.B.*, +, *T-CPMB Aug 96* 532-539

VCSEL-based optoelectronic modules, thermal mgt. *Yung-Cheng Lee*, +, *T-CPMB Aug 96* 540-547

Surface mounting

CMOS μ P, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173

integral decoupling capacitors, time/freq. domain anal. *Goetz, M.P.*, *T-CPMB Aug 96* 518-522

single-mode LD module, pass. alignment. *Kurata, K.*, +, *T-CPMB Aug 96* 524-531

solder joints, fatigue life estim. *Xie, D.J.*, +, *T-CPMB Aug 96* 669-678

solder joints reliab. study, effect of Cu-Sn alloys. *So, A.C.K.*, +, *T-CPMB Aug 96* 661-668

very small peripheral array package, charactn. *Jie Hao*, +, *T-CPMB Aug 96* 512-517

Switching transients

CMOS ccts., simultaneous switching noise, vel. saturation. *Vemuru, S.R.*, *T-CPMB May 96* 344-349

contributions from the 4th IEEE Topical Meeting on Electrical Performance of Electronic Packaging (special section). *T-CPMB Aug 96* 460-522

System reliability; cf. Reliability

T

Testing; cf. Automatic testing; Environmental testing; Manufacturing testing; Materials testing; Reliability testing

Thermal factors

EPBGA packages, cavity-up, thermal perform. *Mertol, A.*, *T-CPMB May 96* 427-443
fully imidized polyimide films, adhesion enhancement and lamination, packaging appls. *Stoffel, N.C.*, +, *T-CPMB May 96* 417-422
surface mount solder joints reliab. study, effect of Cu-Sn alloys. *So, A.C.K.*, +, *T-CPMB Aug 96* 661-668
TAB-OLB contacts, 75 µm pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147

Thermal factors; cf. Integrated circuit thermal factors; Laser thermal factors; Optical fiber thermal factors; Semiconductor device thermal factors; Thermoelasticity; Thermoresistivity

Thermoelasticity

electronic packaging, temp. and stress time hist. responses. *Lau, J.H.*, *T-CPMB Feb 96* 248-254

Thermoresistivity

CMOS µP, hi-dens. C4/CBGA interconnect technol. *Kromann, G.B.*, +, *T-CPMB Feb 96* 166-173
convectively cooled substr., transient thermal response. *Fisher, T.S.*, +, *T-CPMB Feb 96* 255-262
VCSEL-based optoelectronic modules, thermal mgt. *Yung-Cheng Lee*, +, *T-CPMB Aug 96* 540-547

Thick film circuit bonding

multichannel opt. modules compatible, fiber-in-board technol. *De pestel, G.*, +, *T-CPMB Feb 96* 116-123

Thick film circuit fabrication

screen printing resoln. rel., surface energies. *Liang, T.-X.*, +, *T-CPMB May 96* 423-426

Thick film circuit fabrication; cf. Thick film circuit bonding; Thin film circuit bonding

Thin film circuit bonding

multichannel opt. modules compatible, fiber-in-board technol. *De pestel, G.*, +, *T-CPMB Feb 96* 116-123

Thin film circuit interconnections

polyimide-Cu thin-film multilayer interconnects on ceramic substr. *Bedouani, M.*, +, *T-CPMB May 96* 382-390

Thin film inductors

high Q-factor inductors integrated on MCM Si substrs. *Zu, L.*, +, *T-CPMB Aug 96* 635-643

Thin film waveguides; cf. Optical planar waveguides

Time delay; cf. Delay effects

Time difference of arrival estimation; cf. Delay estimation

Time domain analysis

board connector, high pincount, field-based anal. *Wolter, H.*, +, *T-CPMB Feb 96* 23-31

MCM interconnections, freq. and time domain anal. *Salik, R.*, +, *T-CPMB Feb 96* 74-81

Time domain measurements

integral decoupling capacitors, time/freq. domain anal. *Goetz, M.P.*, *T-CPMB Aug 96* 518-522

MLC package, time-domain meas. and cct. modeling. *Jyh-Ming Jong*, +, *T-CPMB Feb 96* 48-56

two-port interconnection struct., cct. modeling, causality. *Sercu, S.*, +, *T-CPMB May 96* 289-295

Time of arrival estimation; cf. Delay estimation

Tin materials/devices

AuSn alloy bonding tech., microwave devices. *Rainer Dohle, G.*, +, *T-CPMB Feb 96* 57-63

AuSn low temp. bonding of epitaxial lift off devices, optoelectronic ICs. *Dohle, G.R.*, +, *T-CPMB Aug 96* 575-580

Cu/Sn-Pb solder joints, interfacial fatigue-crack growth, cooling rate effect. *Daping Yao*, +, *T-CPMB Feb 96* 154-165

poro-free reflow soldering. *Xie, D.J.*, +, *T-CPMB Feb 96* 148-153

surface mount solder joints reliab. study, effect of Cu-Sn alloys. *So, A.C.K.*, +, *T-CPMB Aug 96* 661-668

TAB-OLB contacts, 75 µm pitch, long-term reliab. *Zakel, E.*, +, *T-CPMB Feb 96* 138-147

Transceivers; cf. TR devices

Transfer functions

MCM interconnections, freq. and time domain anal. *Salik, R.*, +, *T-CPMB Feb 96* 74-81

Transient analysis

convectively cooled substr., transient thermal response. *Fisher, T.S.*, +, *T-CPMB Feb 96* 255-262

high-dens. electronic package interconnections, design guidelines. *Yang, Y.*, +, *T-CPMB Feb 96* 230-237

Transient analysis; cf. Circuit transient analysis

Transistor-transistor logic

leadless MCM-D electronic package, 432-pin land-grid I/O array. *Loos, J.S.*, *T-CPMB Feb 96* 174-181

Transition metal materials/devices; cf. Copper materials/devices; Gold materials/devices

Transmission line discontinuities

two-port interconnection struct., cct. modeling, causality. *Sercu, S.*, +, *T-CPMB May 96* 289-295

Transmission line discontinuities; cf. Couplers, Microstrip discontinuities; Optical fiber connectors; Waveguide discontinuities

Transmission line measurements

microelectronic interconnects, transm. line params. meas. *Abernethy, C.E.*, +, *T-CPMB Feb 96* 32-39

Transmission lines; cf. Coupled transmission lines; Multiconductor transmission lines; Planar transmission lines

Transmission line theory

CMOS multilayer substr., transm. line, full wave anal. *Jilin Tan*, +, *T-CPMB Aug 96* 621-627

IC interconnect, multilayer dielec., crossover capacitance. *Guang-Wen Pan*, +, *T-CPMB Aug 96* 615-620

MCM interconnections, freq. and time domain anal. *Salik, R.*, +, *T-CPMB Feb 96* 74-81

Transmitters; cf. Optical transmitters

TR devices

Optobus low-cost high-perform. opt. interconnect. *Schwartz, D.B.*, +, *T-CPMB Aug 96* 532-539

TTL; cf. Transistor-transistor logic

TV cameras; cf. TV image sensors

TV image sensors

epoxy 3D MCM, Design and eval. for portable video equip. *Stern, J.M.*, +, *T-CPMB Feb 96* 188-194

Two-port circuits

two-port interconnection struct., cct. modeling, causality. *Sercu, S.*, +, *T-CPMB May 96* 289-295

U

UHF devices

high Q-factor inductors integrated on MCM Si substrs. *Zu, L.*, +, *T-CPMB Aug 96* 635-643

UHF integrated circuits

high Q-factor inductors integrated on MCM Si substrs. *Zu, L.*, +, *T-CPMB Aug 96* 635-643

UHF spectroscopy

COPNA-resin, low temp. curing resin for high-dens. electronic packages. *Nawa, K.*, +, *T-CPMB Aug 96* 585-592

Ultrafast optics

opto-electronic MCM, polyimide waveguide, LD array packaging. *Koike, S.*, +, *T-CPMB Aug 96* 628-634

Ultra-high-frequency devices; cf. UHF devices

V

Very-large-scale integration

computing inductive noise of CMOS drivers. *Rainal, A.J.*, *T-CPMB Nov 96* 789-802

Level 1 crackfree plastic packaging technol. for VLSI. *Ganesan, G.S.*, +, *T-CPMB Aug 96* 581-584

VLSI interconnect design automation using quantitat. and symbolic techns. *Simunic, T.*, +, *T-CPMB Nov 96* 803-812

Vibrations; cf. Integrated circuit mechanical factors

VLSI; cf. Very-large-scale integration

W

Waveguide discontinuities

MIMIC interconnects, EM field coupling. *Strauss, G.*, +, *T-CPMB May 96* 278-282

Waveguides; cf. Multimode waveguides

Welding; cf. Laser welding

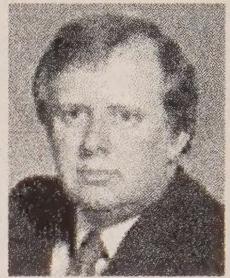
Wiring

sig. pin dens. limitations on wiring boards. *Chiba, T.*, +, *T-CPMB May 96* 391-396

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